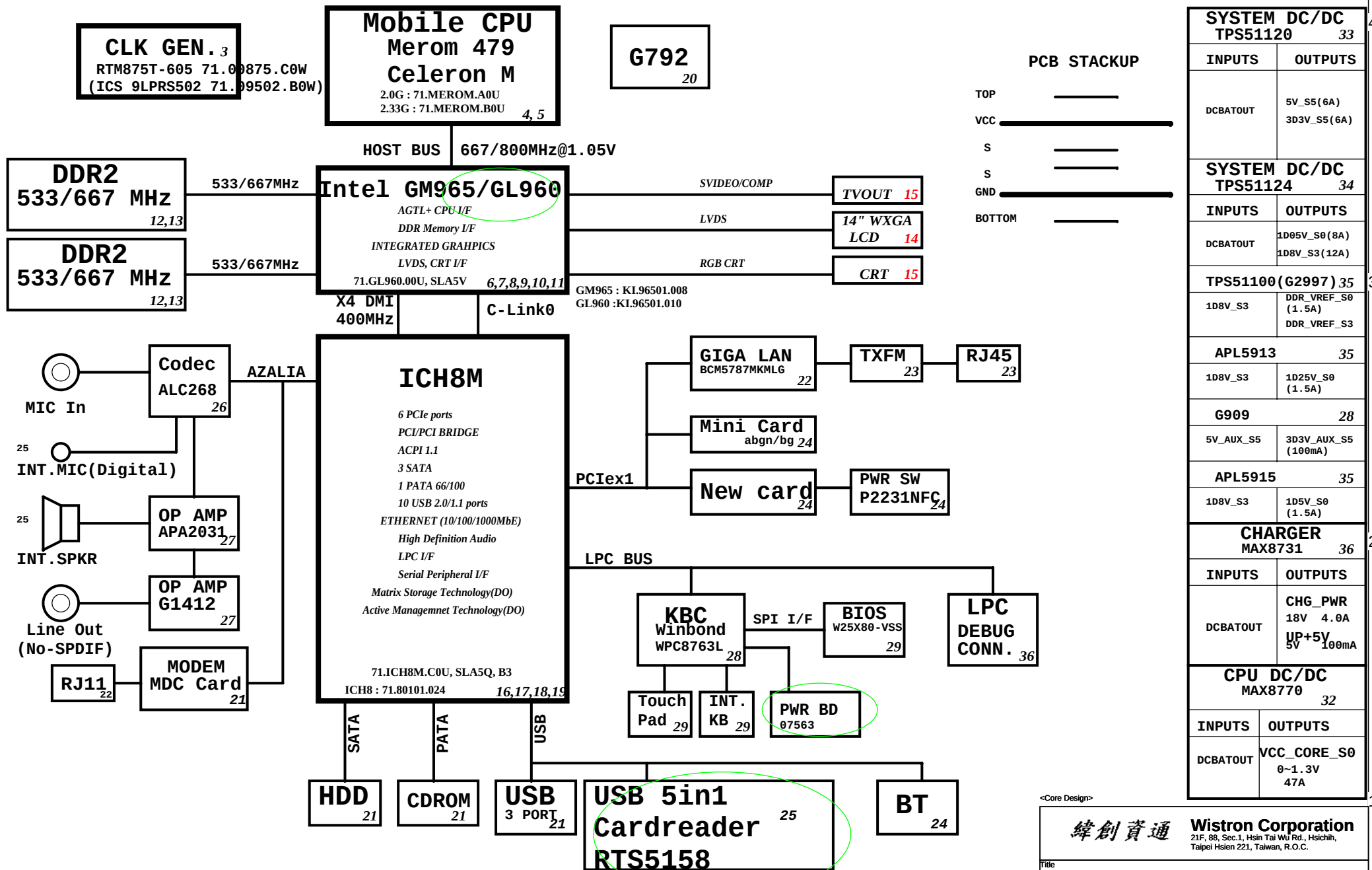


Calado Block Diagram

Project code: 91.4X401.001

PCB P/N : 07227

REVISION : -1



<Core Design>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title			
BLOCK DIAGRAM			
Size	Document Number		Rev
A3	Calado		-1
Date:	Thursday, September 13, 2007	Sheet 1 of 39	

ICH8M Functional Strap Definitions

ICH8-M EDS 21762 2.0V1 page 16

Signal	Usage/When Sampled	Comment
HDA_SDOUT	XOR Chain Entrance/ PCIe Port Config1 bit1, Rising Edge of PWROK	Allows entrance to XOR Chain testing when TP3 pulled low.When TP3 not pulled low at rising edge of PWROK,sets bit1 of RPC.PC(Config Registers: offset 224h)
HDA_SYNC	PCIe config1 bit0, Rising Edge of PWROK.	This signal has a weak internal pull-down. Sets bit0 of RPC.PC(Config Registers:Offset 224h)
GNT2#	PCIe config2 bit0, Rising Edge of PWROK.	This signal has a weak internal pull-up. Sets bit2 of RPC.PC2(Config Registers:Offset 0224h)
GPI020	Reserved	This signal should not be pulled high.
GNT1#/ GPI051	ESI Strap (Server Only) Rising Edge of PWROK	ESI compatible mode is for server platforms only. This signal should not be pulled low for desttop and mobile.
GNT3#	Top-Block Swap Override. Rising Edge of PWROK.	Sampled low:Top-Block Swap mode(inverts A16 for all cycles targeting FWH BIOS space). Note: Software will not be able to clear the Top-Swap bit until the system is rebooted without GNT3# being pulled down.
GNT0#/ SPI_CS1#	Boot BIOS Destination Selection. Rising Edge of PWROK.	Controllable via Boot BIOS Destination bit (Config Registers:Offset 3410h:bit 11:10). GNT0# is MSB, 01-SPI, 10-PCI, 11-LPC.
INTVRMEN	Integrated VccSusi_05, VccSusi_5 and VccCL1_5 VRM Enable/Disable. Always sampled.	Enables integrated VccSusi_05, VccSusi_5 and VccCL1_5 VRM's when sampled high
LAN100_SLP	Integrated VccLAN1_05 and VccCL1_05 VRM Enable/Disable. Always sampled.	Enables integrated VccLAN1_05 and VccCL1_05 VRM's when sampled high
SATALED#	PCI Express Lane Reversal. Rising Edge of PWROK.	Signal has weak internal pull-up. Sets bit 27 of MPC.LR(Device 28:Function 0:Offset D8)
SPKR	No Reboot. Rising Edge of PWROK.	If sampled high, the system is strapped to the "No Reboot" mode(ICH8 will disable the TCO Timer system reboot feature). The status is readable via the NO REBOOT bit.
TP3	XOR Chain Entrance. Rising Edge of PWROK.	This signal should not be pull low unless using XOR Chain testing.
GPI033/ HDA_DOCK _EN#	Flash Descriptor Security Override Strap Rising Edge of PWROK	This signal has a weak internal pull-up. Sampled low:the Flash Descriptor Security will be overridden. If high,the security measures will be in effect.This should only be used in manufacturing environments.

ICH8M IDE Integrated Series Termination Resistors

DD[15:0], DIOw#, DIOR#, DREQ, DDACK#, IORDY, DA[2:0], DCS1#, DCS3#, IDEIRQ	approximately 33 ohm
--	----------------------

PCIE Routing

LANE1	LAN Marvell
LANE2	MiniCard WLAN
LANE3	NewCard WLAN

USB Table

USB	
Pair	Device
0	USB1
1	NC
2	USB2
3	NC
4	USB3
5	BT
6	Cardreader
7	MINICARD
8	CCD
9	NEW1

ICH8M Integrated Pull-up and Pull-down Resistors

ICH8-M EDS 21762 2.0V1

SIGNAL	Resistor Type/Value
HDA_BIT_CLK	PULL-DOWN 20K
HDA_RST#	NONE
HDA_SDIN[3:0]	PULL-DOWN 20K
HDA_SDOUT	PULL-DOWN 20K
HDA_SYNC	PULL-DOWN 20K
GNT[3:0]	PULL-UP 20K
GPI0[20]	PULL-DOWN 20K ?
LDA[3:0]#/FHW[3:0]#	PULL-UP 20K
LAN_RXD[2:0]	PULL-UP 10K
LDRQ[0]	PULL-UP 20K
LDRQ[1]/GPI023	PULL-UP 20K
PME#	PULL-UP 20K
PWRBTN#	PULL-UP 20K
SATALED#	PULL-UP 15K
SPI_CS1#	PULL-UP 20K
SPI_CLK	PULL-UP 20K
SPI_MOSI	PULL-UP 20K
SPI_MISO	PULL-UP 20K
TACH_[3:0]	PULL-UP 20K ?
SPKR	PULL-DOWN 20K
TP[3]	PULL-UP 20K
USB[9:0][P,N]	PULL-DOWN 15K
CL_RST#	PULL-UP 13K

History

Crestline Strapping Signals and Configuration

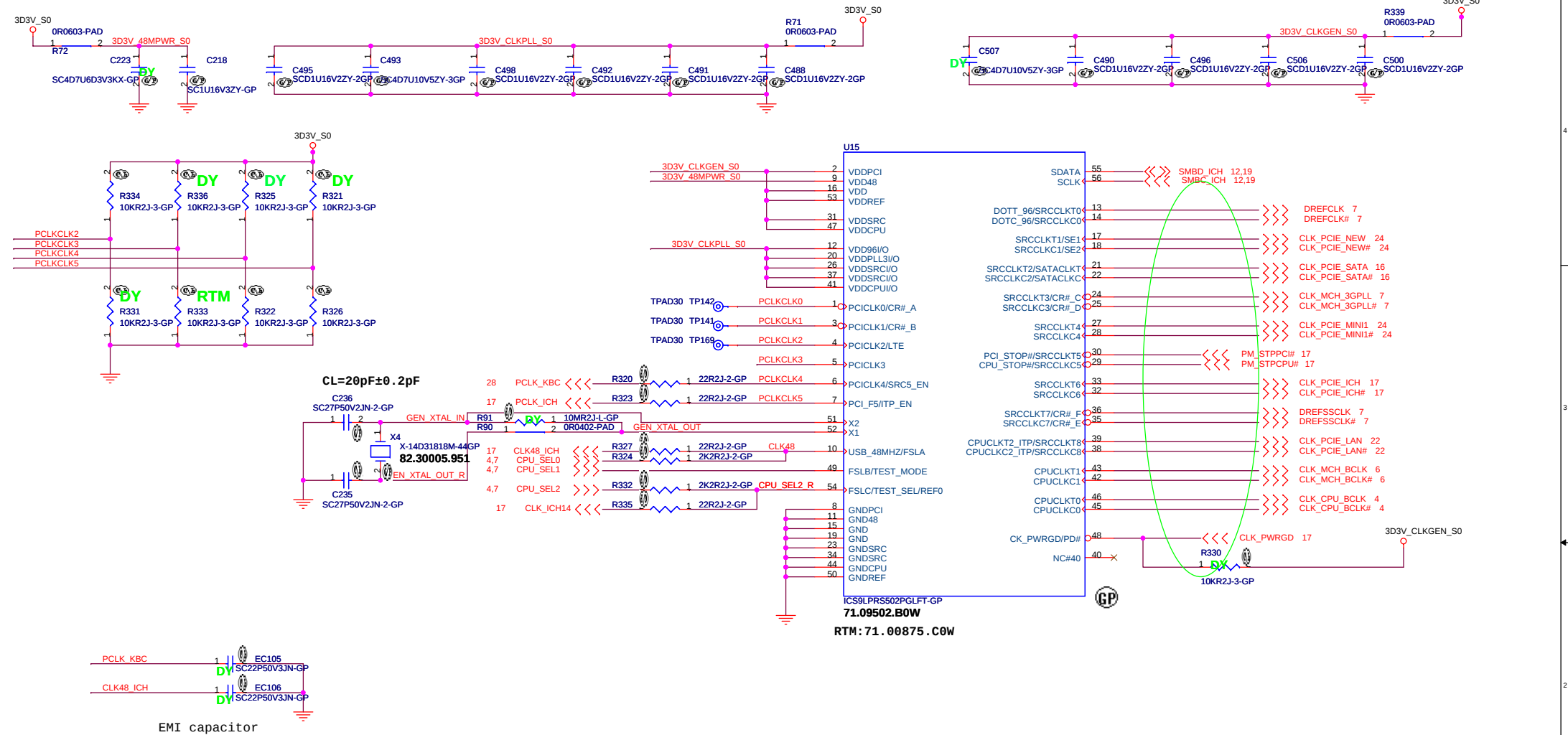
Crestline EDS 20954 1.0 page 7

Pin Name	Strap Description	Configuration
CFG[2:0]	FSB Frequency Select	001 = FSB533 011 = FSB667 010 = FSB800 others = Reserved
CFG[4:3]	Reserved	
CFG5	DMI x2 Select	0 = DMI x2 1 = DMI x4 (Default)
CFG[8:6]	Reserved	
	Low Power PCI Express	0 = Normal mode 1 = Low Power mode (Default)
CFG9	PCI Express Graphics Lane Reversal	0 = Reverse Lanes,15->0,14->1 ect.. 1= Normal operation(Default):Lane Numbered in order
CFG[11:10]	Reserved	
CFG[13:12]	XOR/ALL Z test straps	00 = Reserved 01 = XOR mode enabled 10 = All Z mode enabled 11 = Normal Operation (Default)
CFG[15:14]	Reserved	
CFG16	FSB Dynamic ODT	0 = Dynamic ODT Disabled 1 = Dynamic ODT Enabled (Default)
CFG[18:17]	Reserved	
CFG19	DMI Lane Reversal	0 = Normal operation (Default):lane Numbered in order 1 =Reverse Lane,4->0,3->1 ect...
CFG20	SDVO/PCIE Concurrent	0 = Only SDVO or PCIE x1 is operational (Default) 1 =SDVO and PCIE x1 are operating simultaneously via the PEG port
SDVOCRTL_DATA	SDVO Present	0 = No SDVO Card present (Default) 1= SDVO Card present

NOTE: All strap signals are sampled with respect to the leading edge of the Crestline GMCH PWORK in signal.

<Core Design>

緯創資通		Wistron Corporation	
21F, 80, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.			
Title			
Reference			
Size	Document Number	Rev	
A3		-1	
Date:	Monday, September 10, 2007	Sheet	2 of 39



ICS9LPR502HGLFT-GP setting table

PIN NAME	DESCRIPTION
PCI0/CR#_A	Byte 5, bit 7 0 = PCI0 enabled (default) 1= CR#_A enabled. Byte 5, bit 6 controls whether CR#_A controls SRC0 or SRC2 pair Byte 5, bit 6 0 = CR#_A controls SRC0 pair (default), 1= CR#_A controls SRC2 pair
PCI1/CR#_B	Byte 5, bit 5 0 = PCI1 enabled (default) 1= CR#_B enabled. Byte 5, bit 6 controls whether CR#_B controls SRC1 or SRC4 pair Byte 5, bit 4 0 = CR#_B controls SRC1 pair (default) 1= CR#_B controls SRC4 pair
PCI2/TME	0 = Overclocking of CPU and SRC Allowed 1 = Overclocking of CPU and SRC NOT allowed
PCI4/SRC5_EN	0 = Pin29 as CPU_STOP#, pin 30 as PCI_STOP#. 1 = Pins29,30 as SRC-5 differential pair.
PCI_F5/ITP_EN	0 = SRC8/SRC8# 1 = ITP/ITP#

RTM875T-605 setting table

PIN NAME	DESCRIPTION
PCI0/CR#_A	Byte 5, bit 7 0 = PCI0 enabled (default) 1= CR#_A enabled. Byte 5, bit 6 controls whether CR#_A controls SRC0 or SRC2 pair Byte 5, bit 6 0 = CR#_A controls SRC0 pair (default), 1= CR#_A controls SRC2 pair
PCI1/CR#_B	Byte 5, bit 5 0 = PCI1 enabled (default) 1= CR#_B enabled. Byte 5, bit 6 controls whether CR#_B controls SRC1 or SRC4 pair Byte 5, bit 4 0 = CR#_B controls SRC1 pair (default) 1= CR#_B controls SRC4 pair
PCI2/TME	0 = Overclocking of CPU and SRC Allowed 1 = Overclocking of CPU and SRC NOT allowed
PCI3/SRC-5_EN	0 = Pin29 as CPU_STOP# , pin 30 as PCI_STOP#. 1 = Pins29,30 as SRC-5 differential pair.
PCI4/27M_SEL	0 = Pin17 as SRC-1, Pin18 as SRC-1#, Pin13 as DOT96, Pin14 as DOT96# 1 = Pin17 as 27MHz, Pin 18 as 27MHz_SS, Pin13 as SRC-0, Pin14 as SRC-0#
PCI_F5/ITP_EN	0 = SRC8/SRC8# 1 = ITP/ITP#

SEL2 FSC	SEL1 FSB	SEL0 FSA	CPU	FSB
1	0	1	100M	X
0	0	1	133M	X
0	1	1	166M	667M
0	1	0	200M	800M

<Core Design>

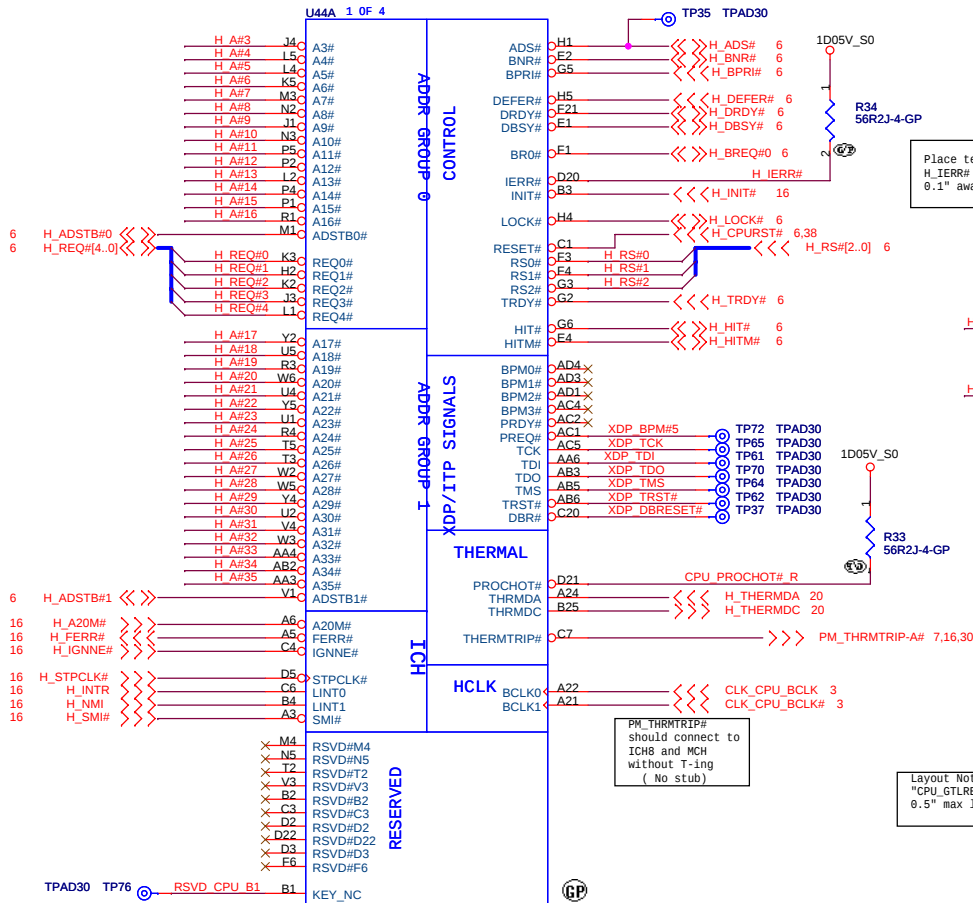
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taippei Hsien 221, Taiwan, R.O.C.

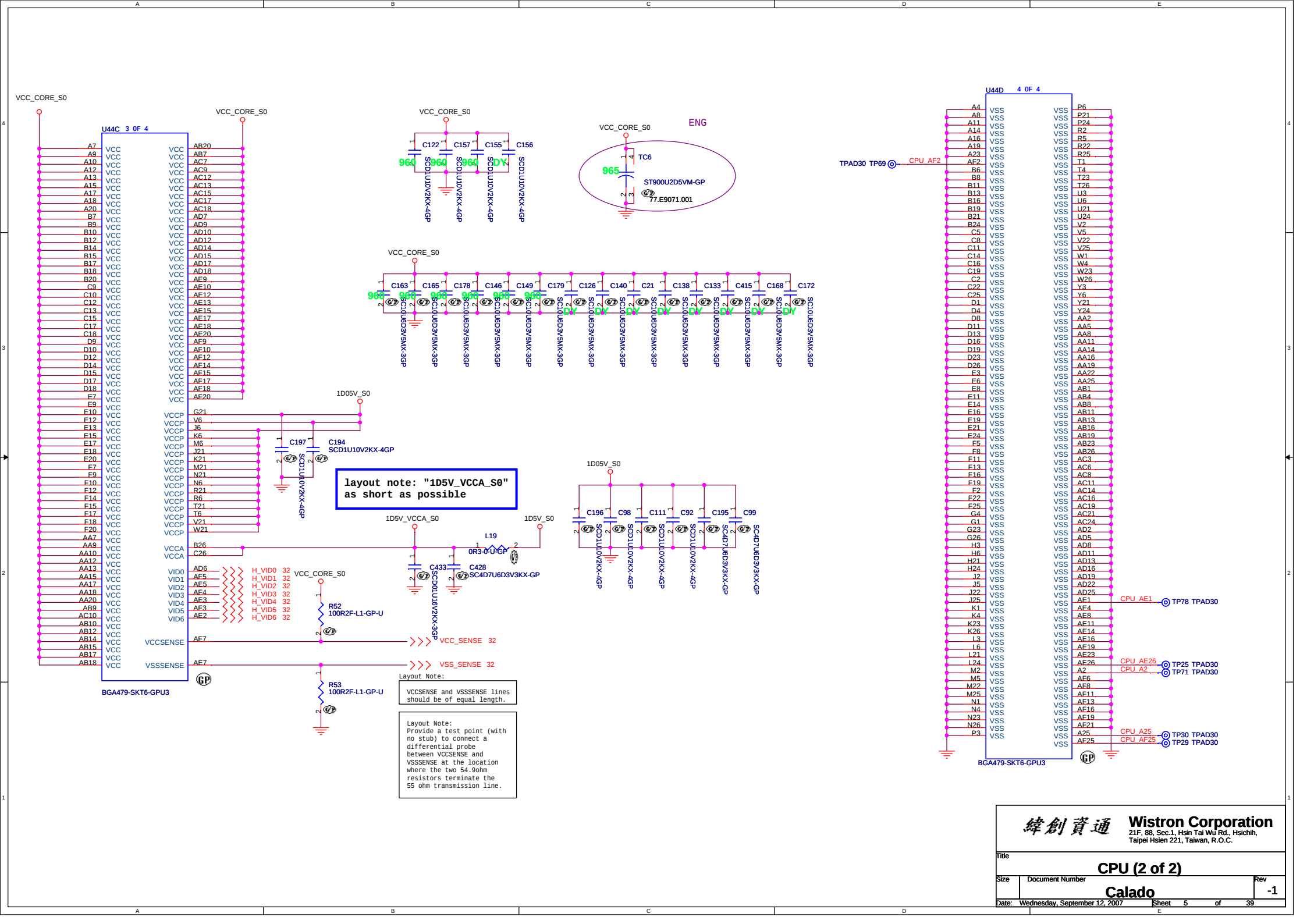
Title: **Clock Generator**

Size: Document Number: **Calado** Rev: **-1**

Date: Wednesday, September 12, 2007 Sheet 3 of 39

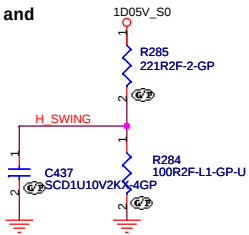
6 H_A#(35..3) <<>> H_A#(35..3)



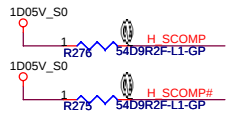


H_SWING routing Trace width and Spacing use 10 / 20 mil

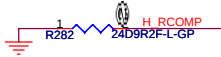
H_SWING Resistors and Capacitors close MCH 500 mil (MAX)



H_SCOMP and H_SCOMP# Resistors and Capacitors close MCH 500 mil (MAX)

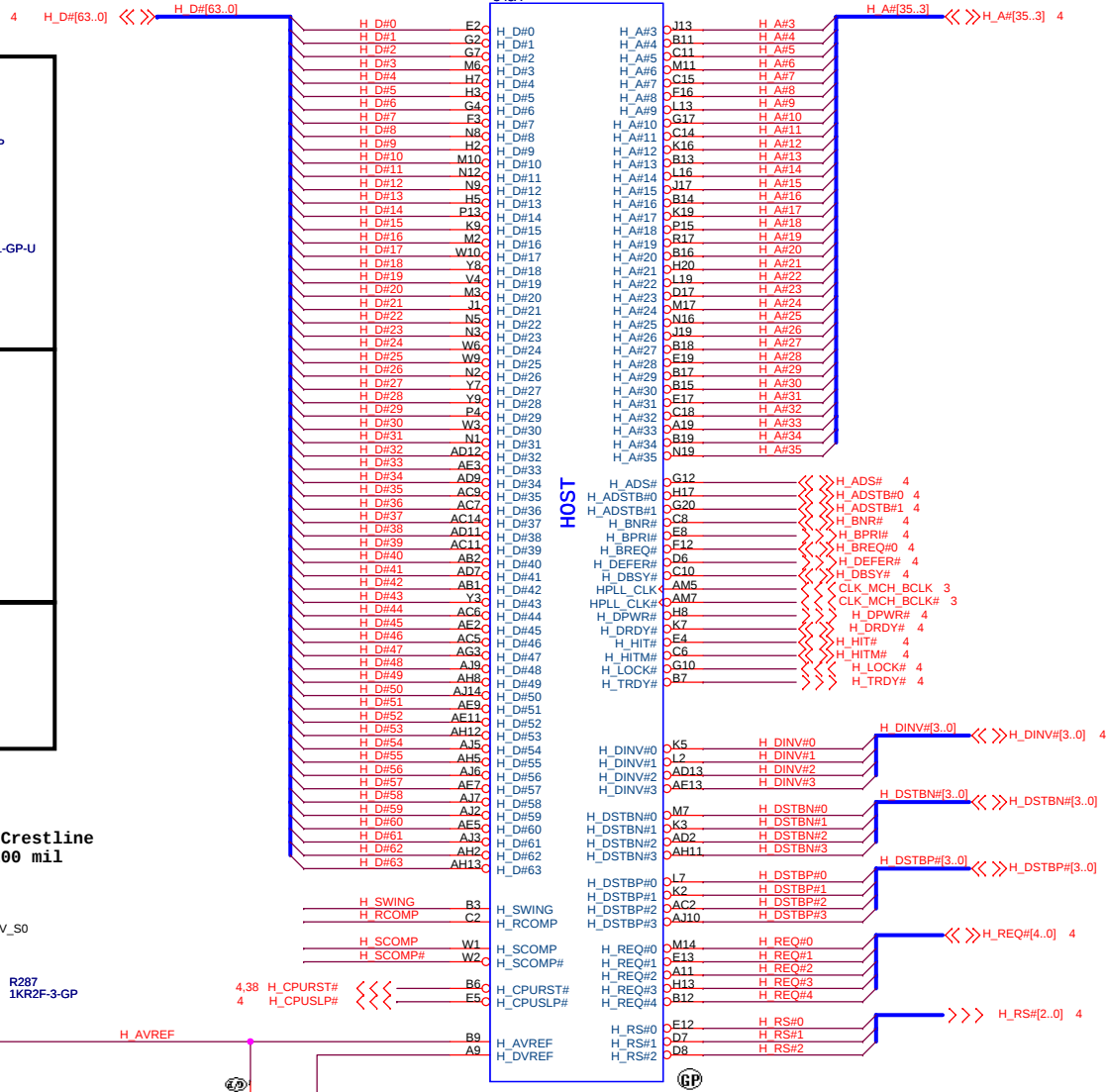
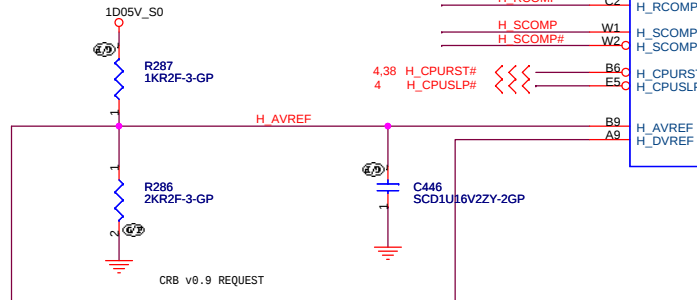


H_RCOMP routing Trace width and Spacing use 10 / 20 mil



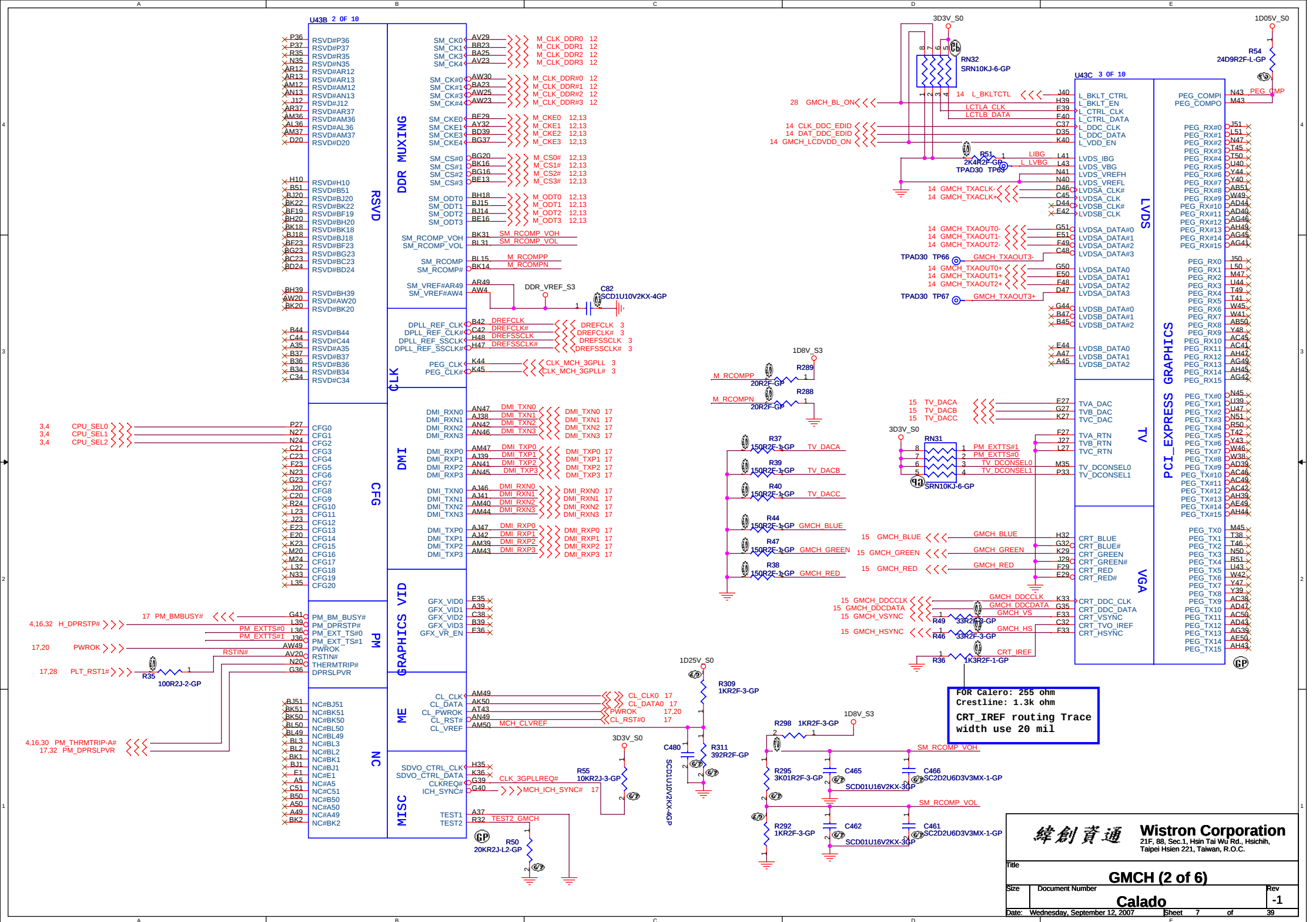
Place them near to the chip (< 0.5")

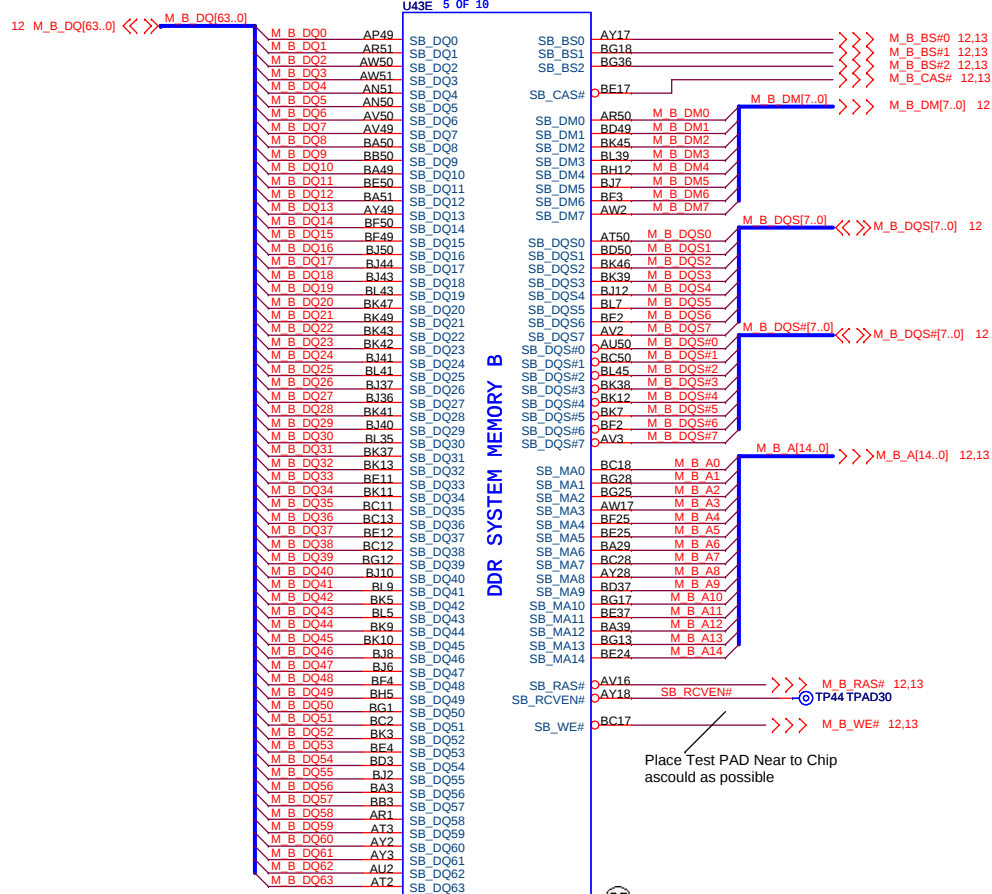
H_REF Decoupling Crestline close Crestline 100 mil



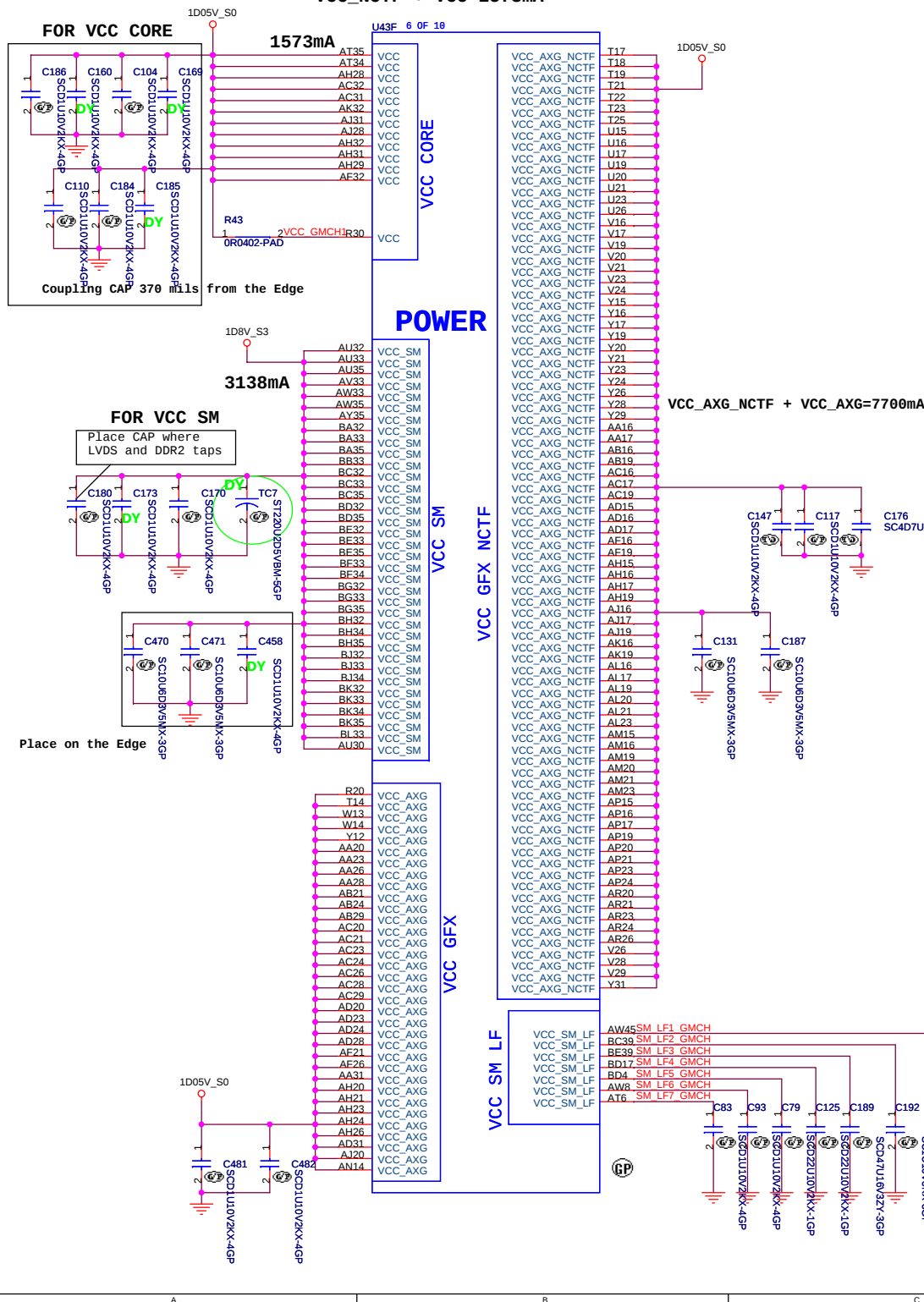
<Core Design>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichin,
Taipei Hsien 221, Taiwan, R.O.C.

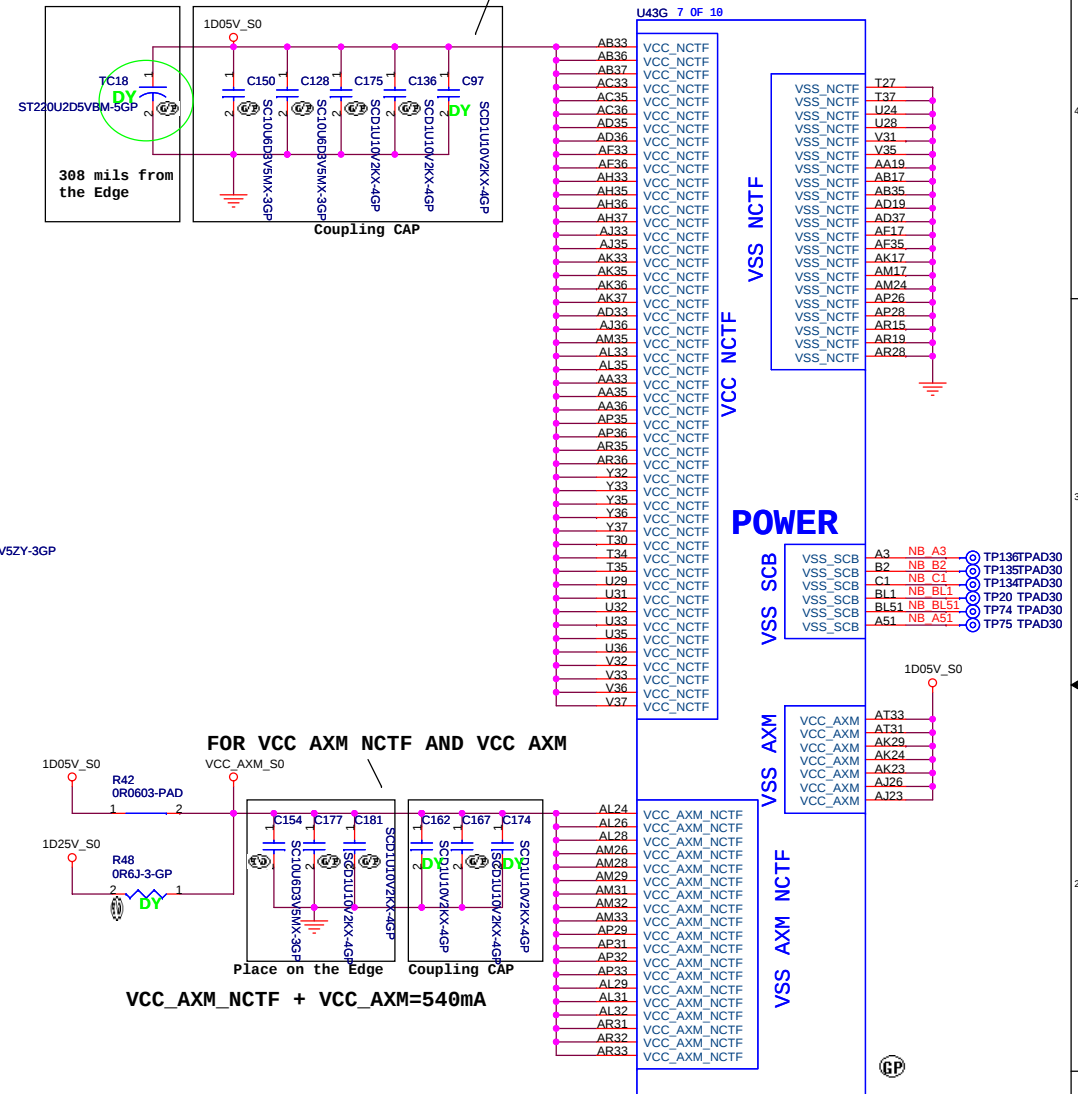


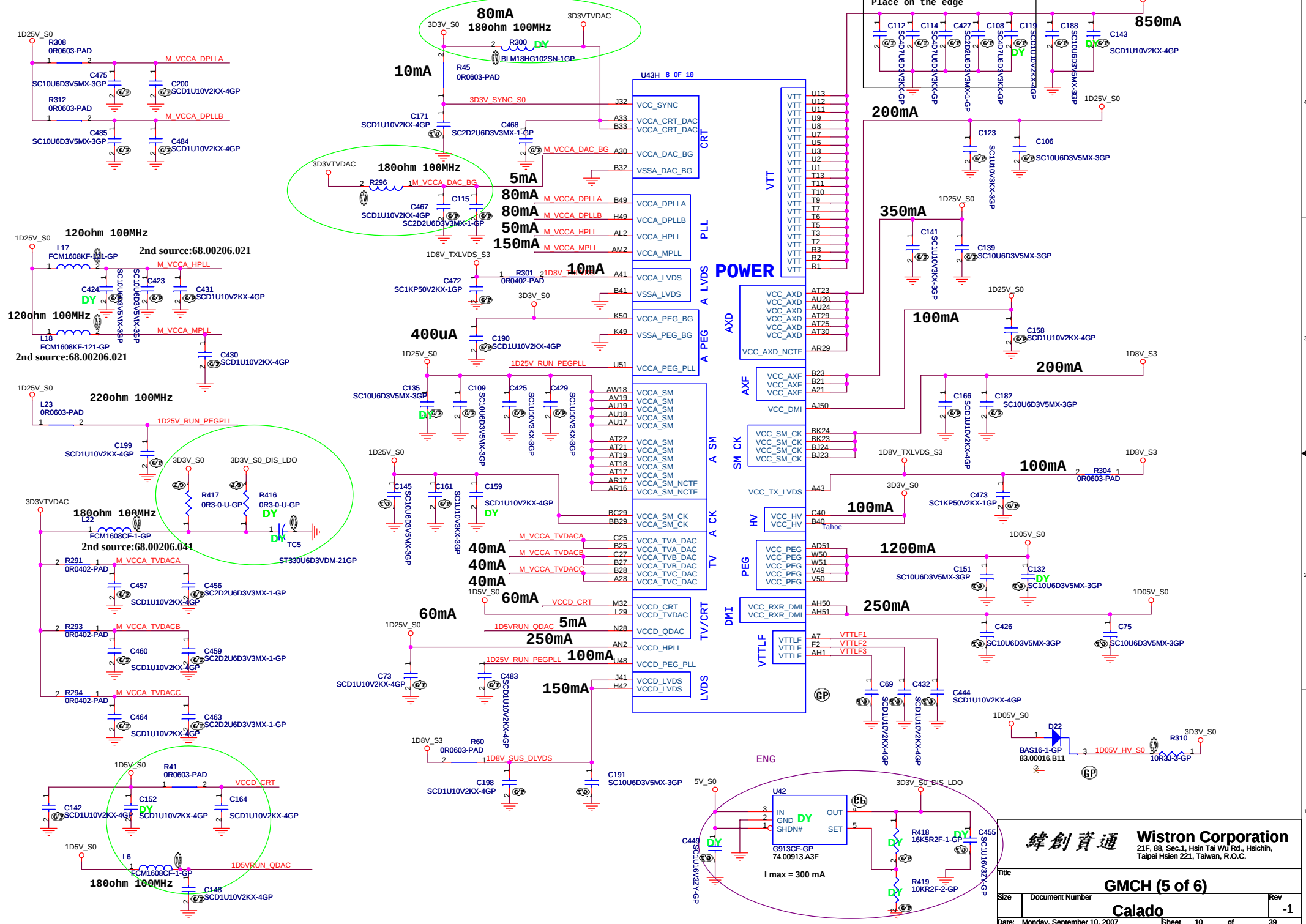


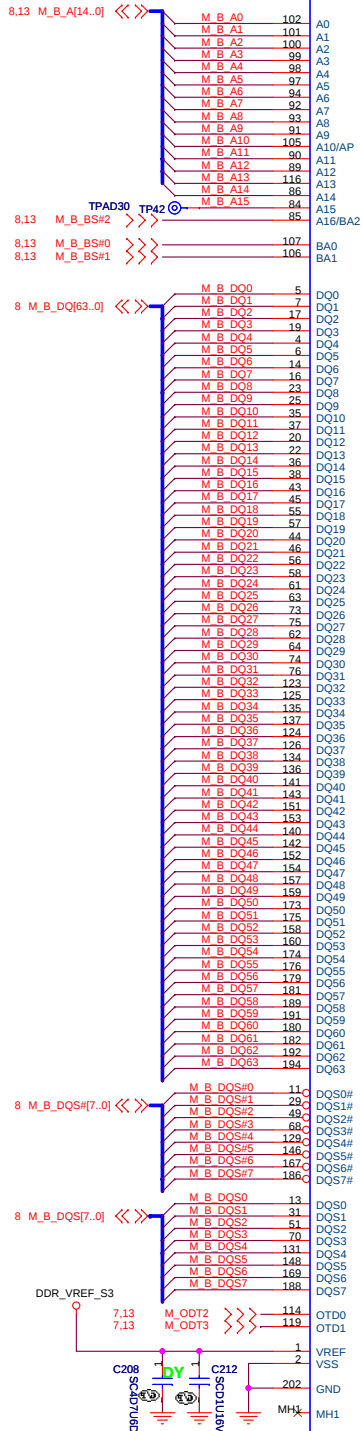
VCC_NCTF + VCC=1573mA



FOR VCC CORE AND VCC NCTF

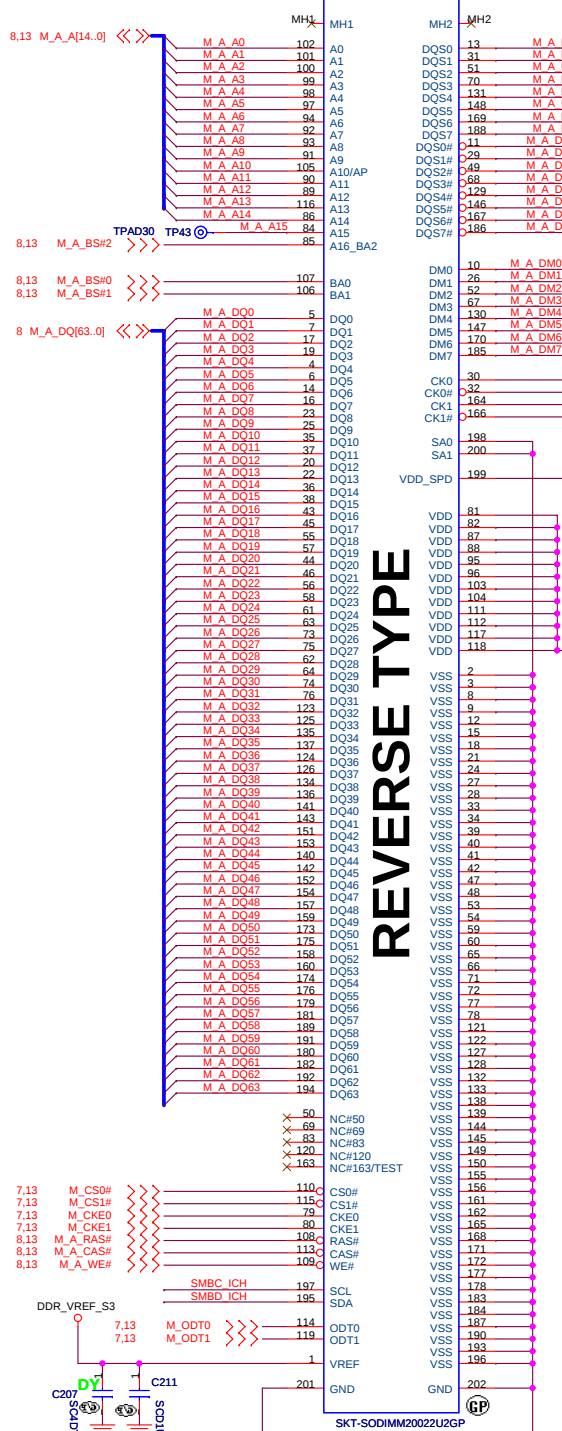
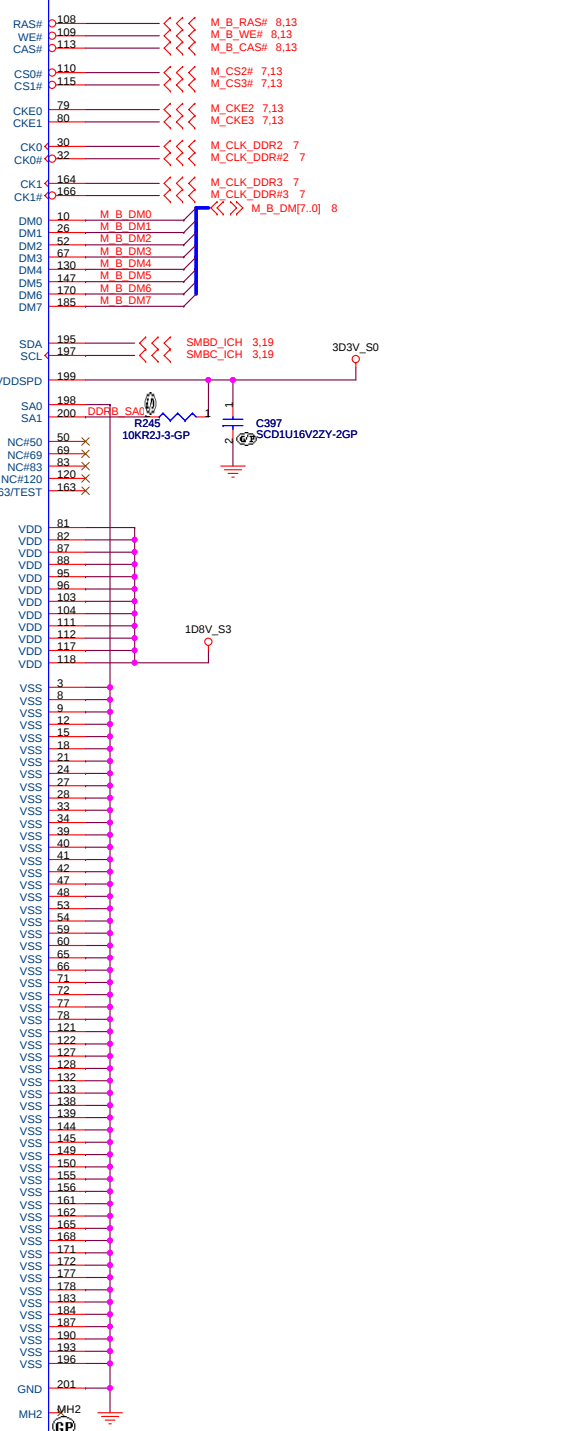






REVERSE TYPE

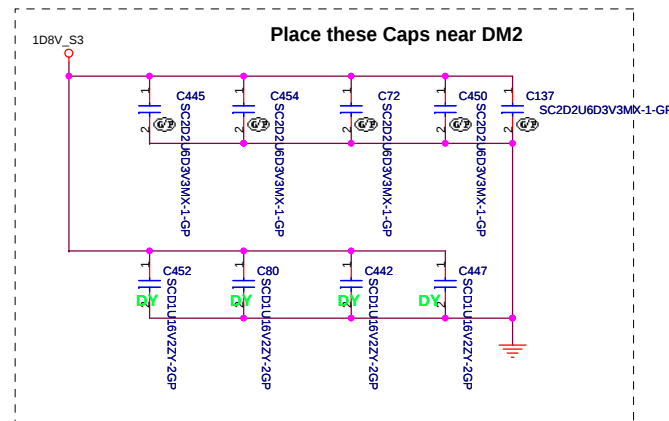
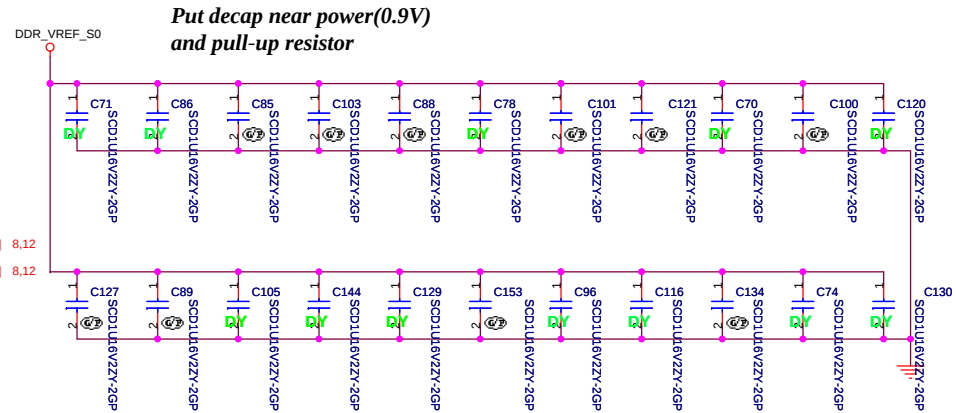
DDR2-200P-23-GP-U1
62.10017.A71
High 9.2mm



REVERSE TYPE

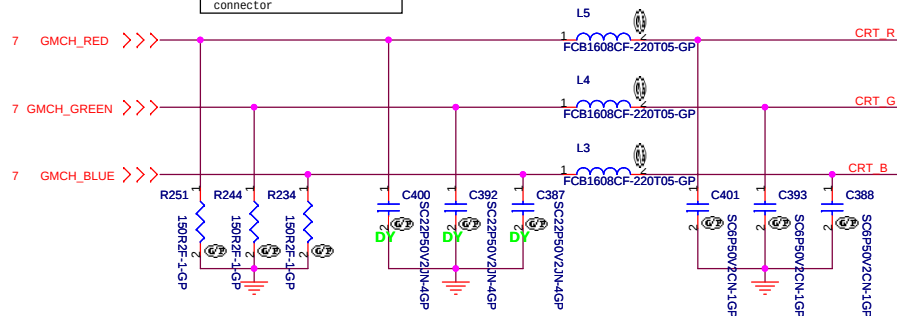
DDR2-200P-23-GP-U1
62.10017.A71
High 5.2mm

Decoupling Capacitor

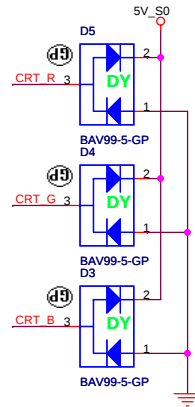


Layout Note:
Place these resistors
close to the CRT-out
connector

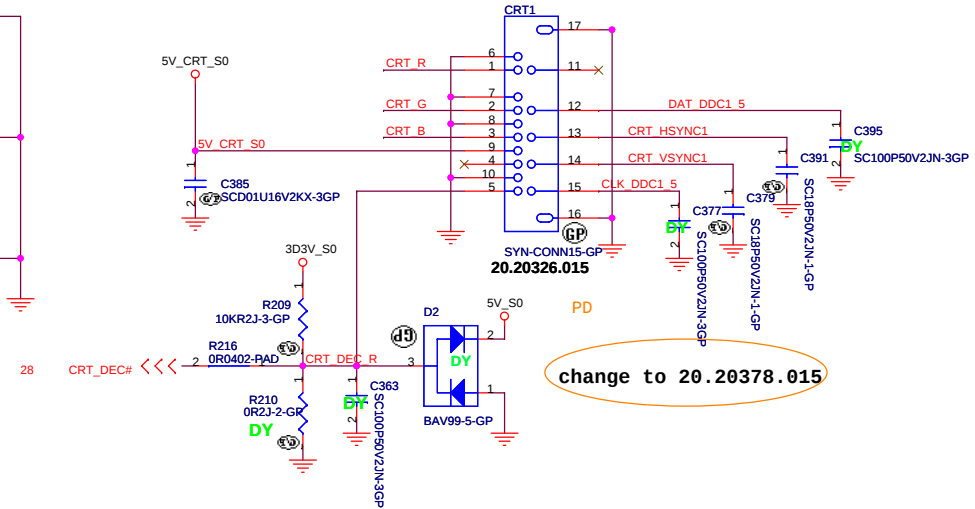
Ferrite bead impedance: 22 ohm@100MHz
from 10 ohm change to 22 ohm for EMI



Layout Note:
* Must be a ground return path between this ground and the ground on the VGA connector.
Pi-filter & 150 Ohm pull-down resistors should be as close as to CRT CONN. RGB will hit 75 Ohm first, pi-filter, then CRT CONN.

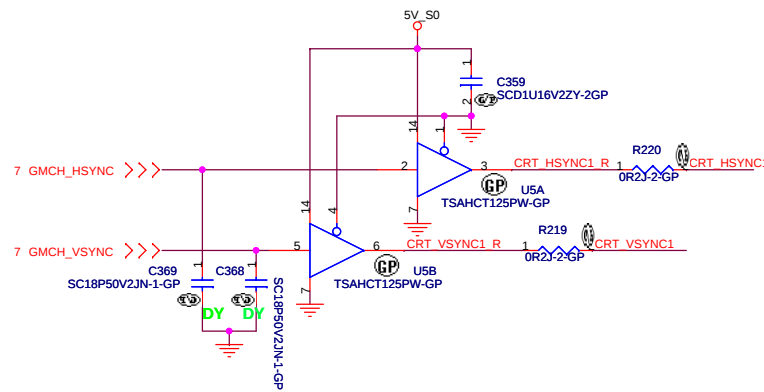


CRT I/F & CONNECTOR

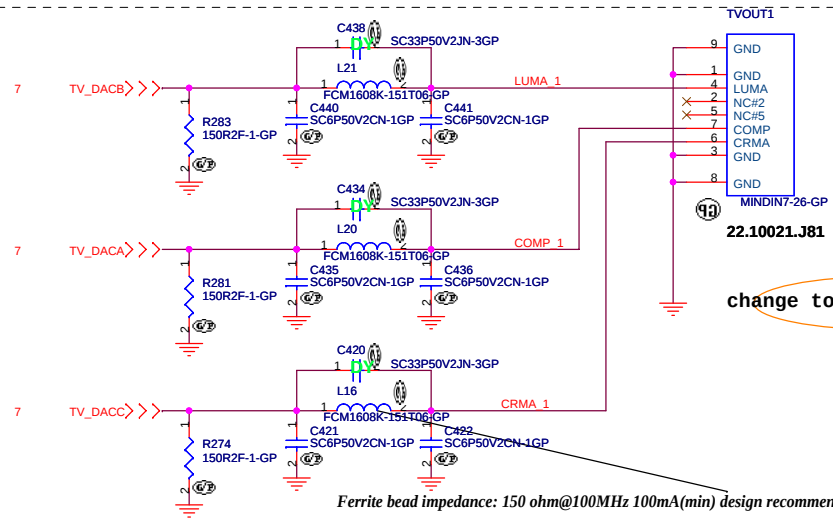


change to 20.20378.015

Hsync & Vsync level shift

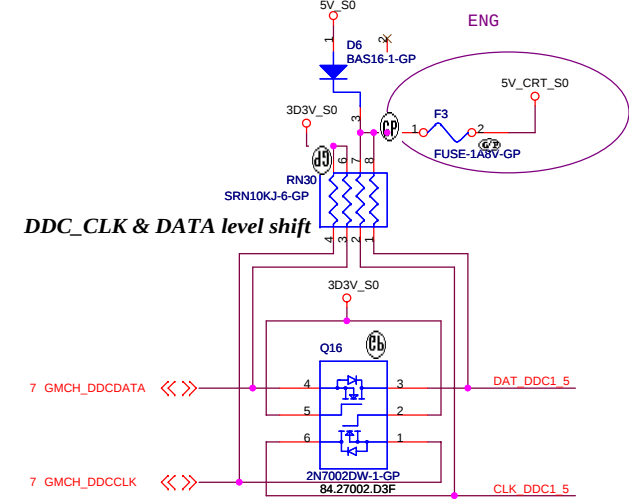


TV CONN



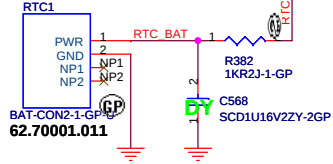
change to 22.10021.H61

Ferrite bead impedance: 150 ohm@100MHz 100mA(min) design recommend



緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

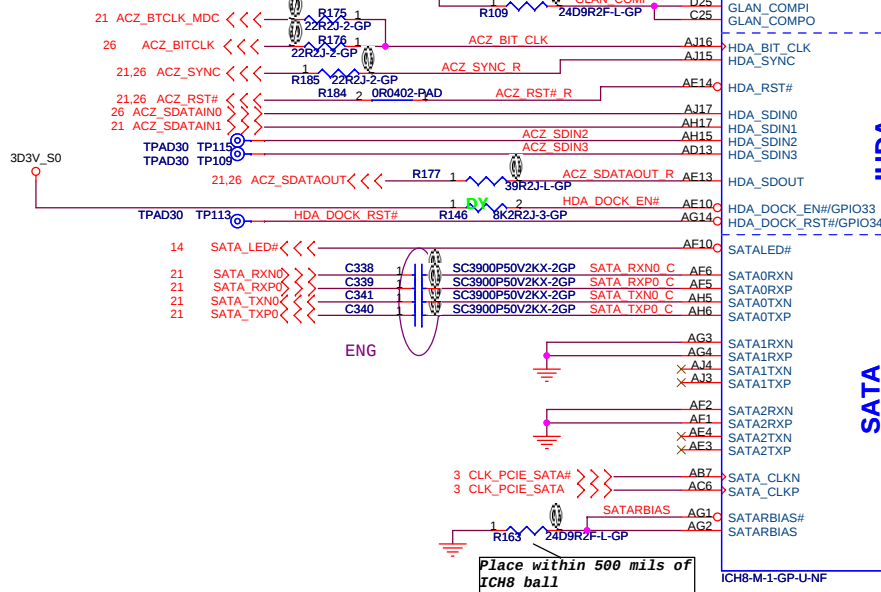
RTC circuitry



EMI capacitor

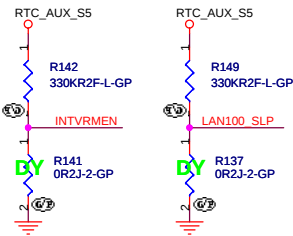


GLAN_COMP place within 500 mil of ICH8M



Place within 500 mils of ICH8 ball

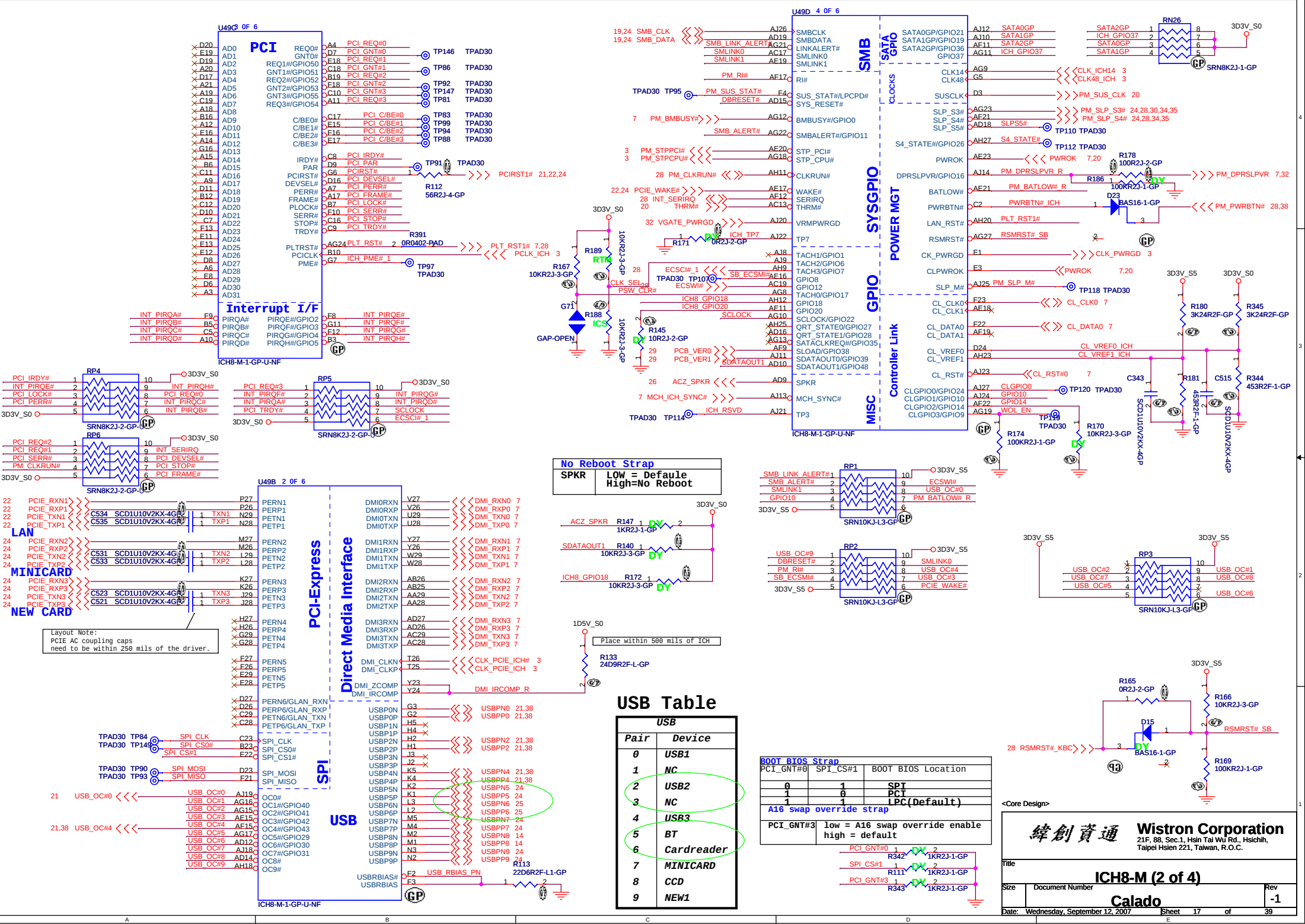
Change to 24.9 1% ohm when use SATA HD



Integrated VccSus1_05,VccSus1_5,VccCl1_5		
INTVRMEN	High=Enable	Low=Disable
Integrated VccLan1_05VccCl1_05		
LAN100_SLP	High=Enable	Low=Disable

<Core Design>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.



No Reboot Strap
SPKR LOW = Default
High = No Reboot

USB Table

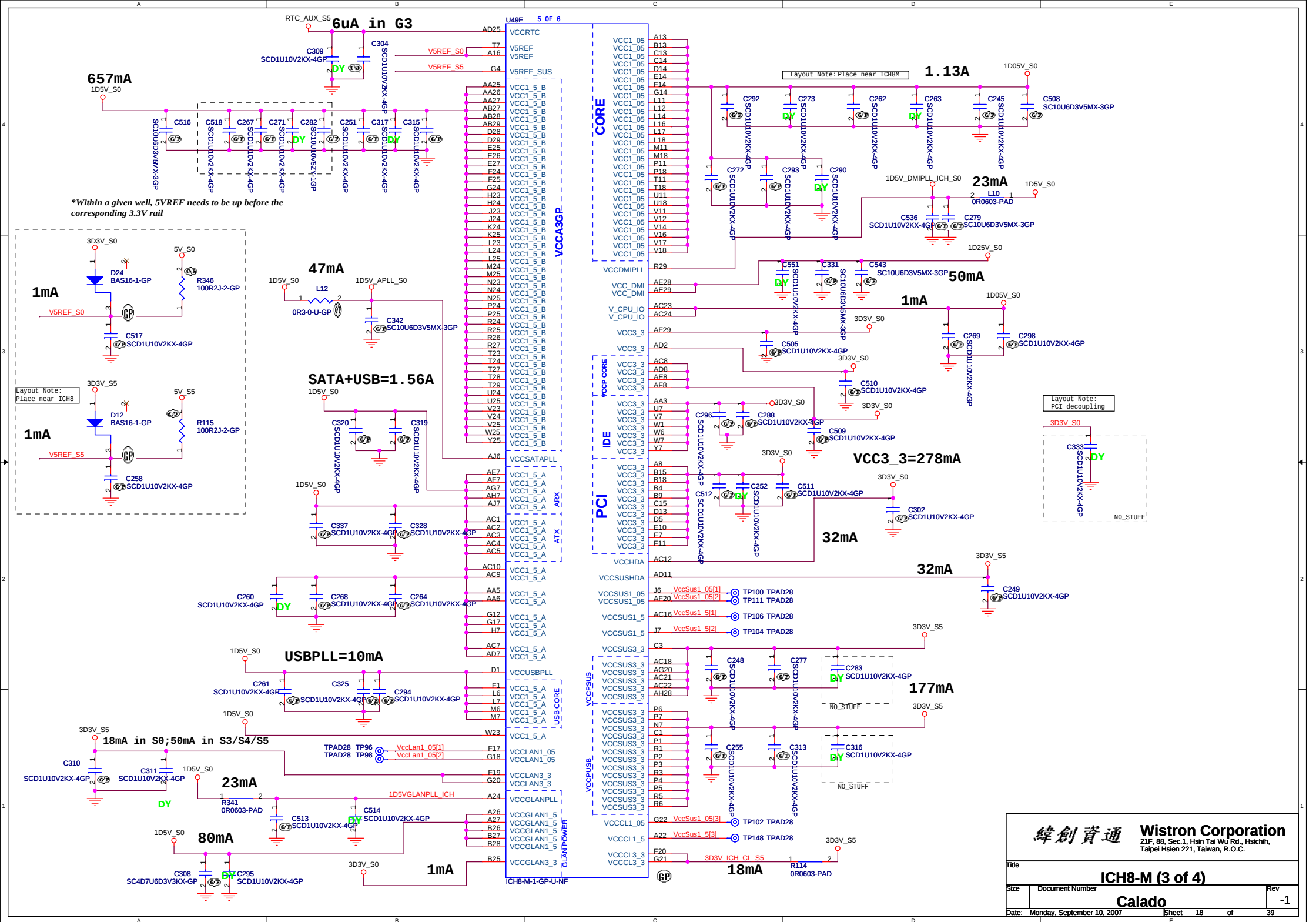
USB	
Pair	Device
0	USB1
1	NC
2	USB2
3	NC
4	USB3
5	BT
6	Cardreader
7	MINICARD
8	CCD
9	NEW1

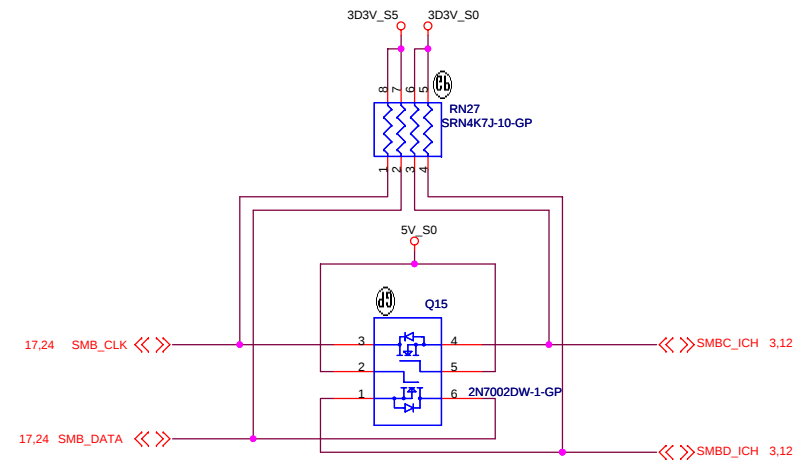
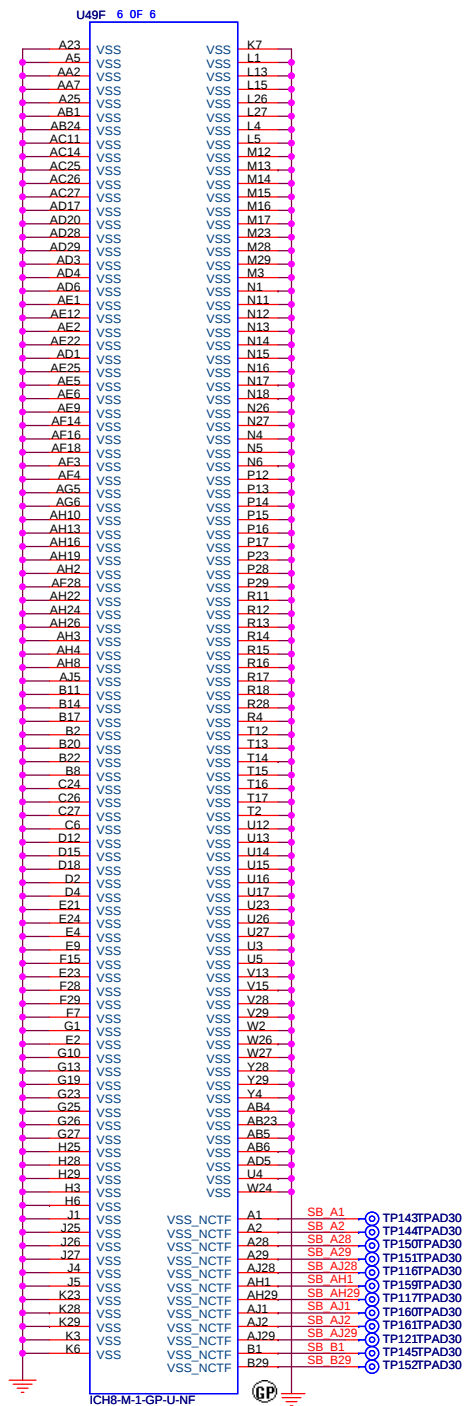
BOOT BIOS Strap		
PCI_GNT#0	SPI_CS#1	BOOT BIOS Location
0	1	SPT
1	0	PCI
A16 swap override strap		
PCI_GNT#3	low = A16 swap override enable high = default	

緯創資通 Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichin, Taipei Hsien 221, Taiwan, R.O.C.

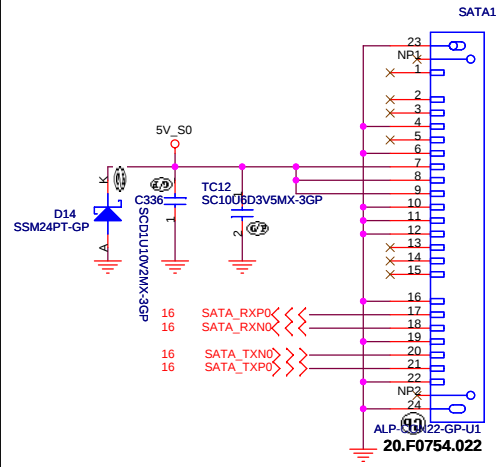
Title		ICH8-M (2 of 4)	
Size	Document Number	Rev -1	
Date: Wednesday, September 12, 2007		Sheet 17	of 39



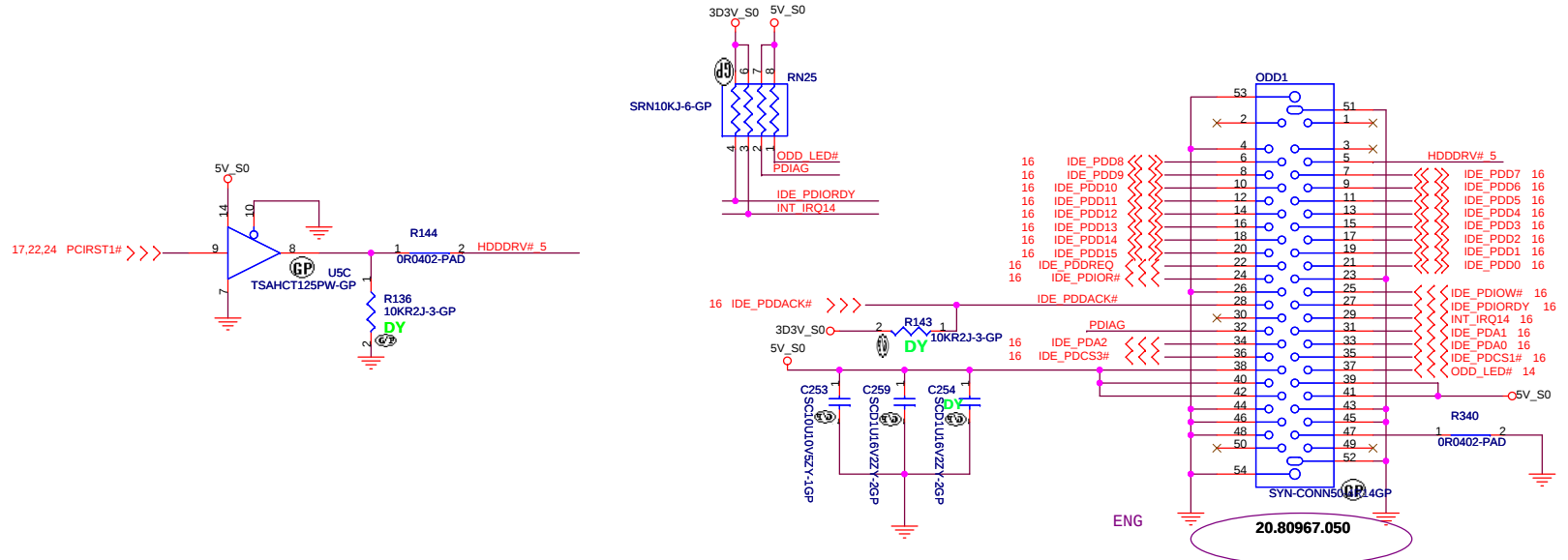


SMBUS

SATA HD Connector

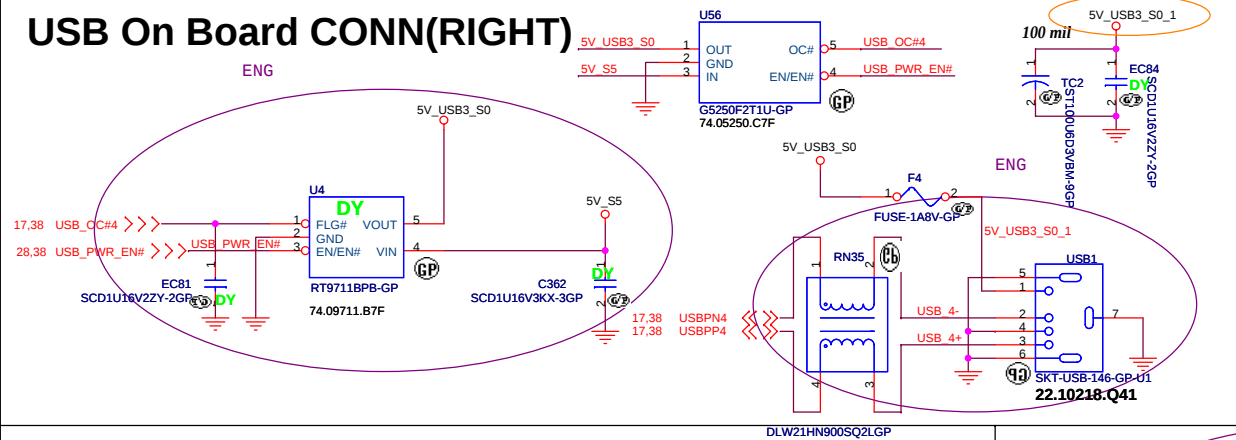


ODD Connector

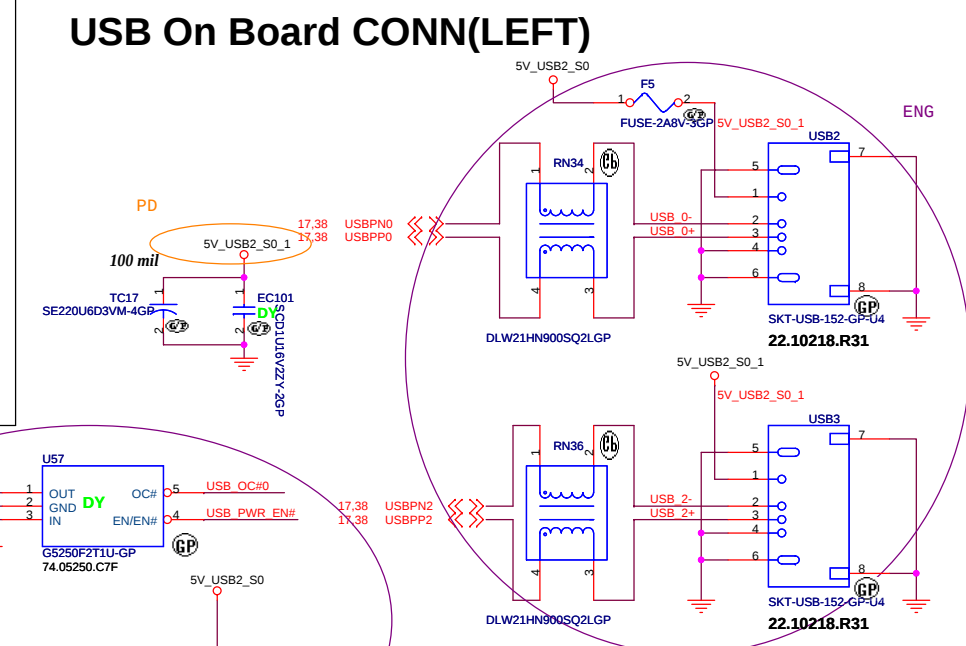


PD

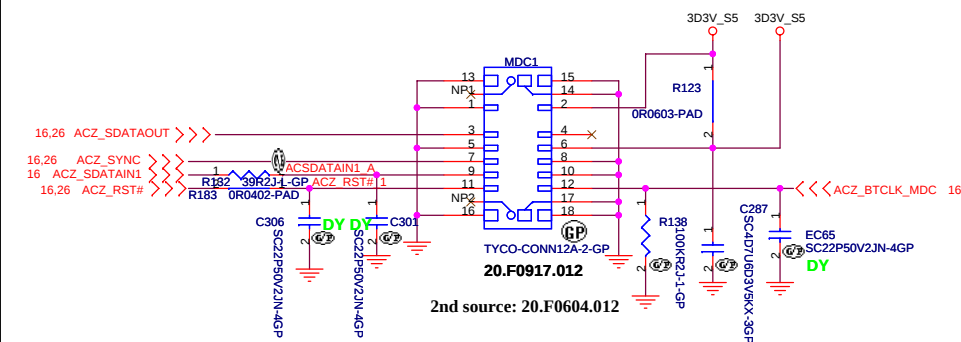
USB On Board CONN(RIGHT)



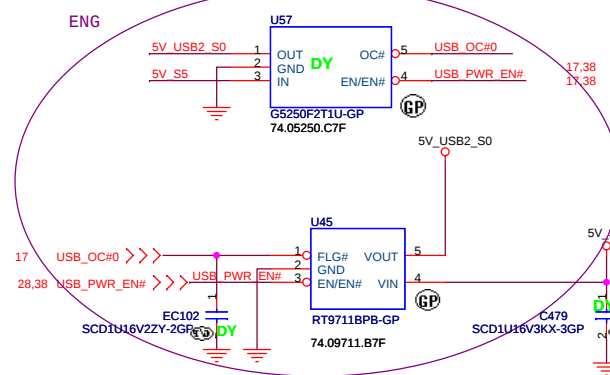
USB On Board CONN(LEFT)

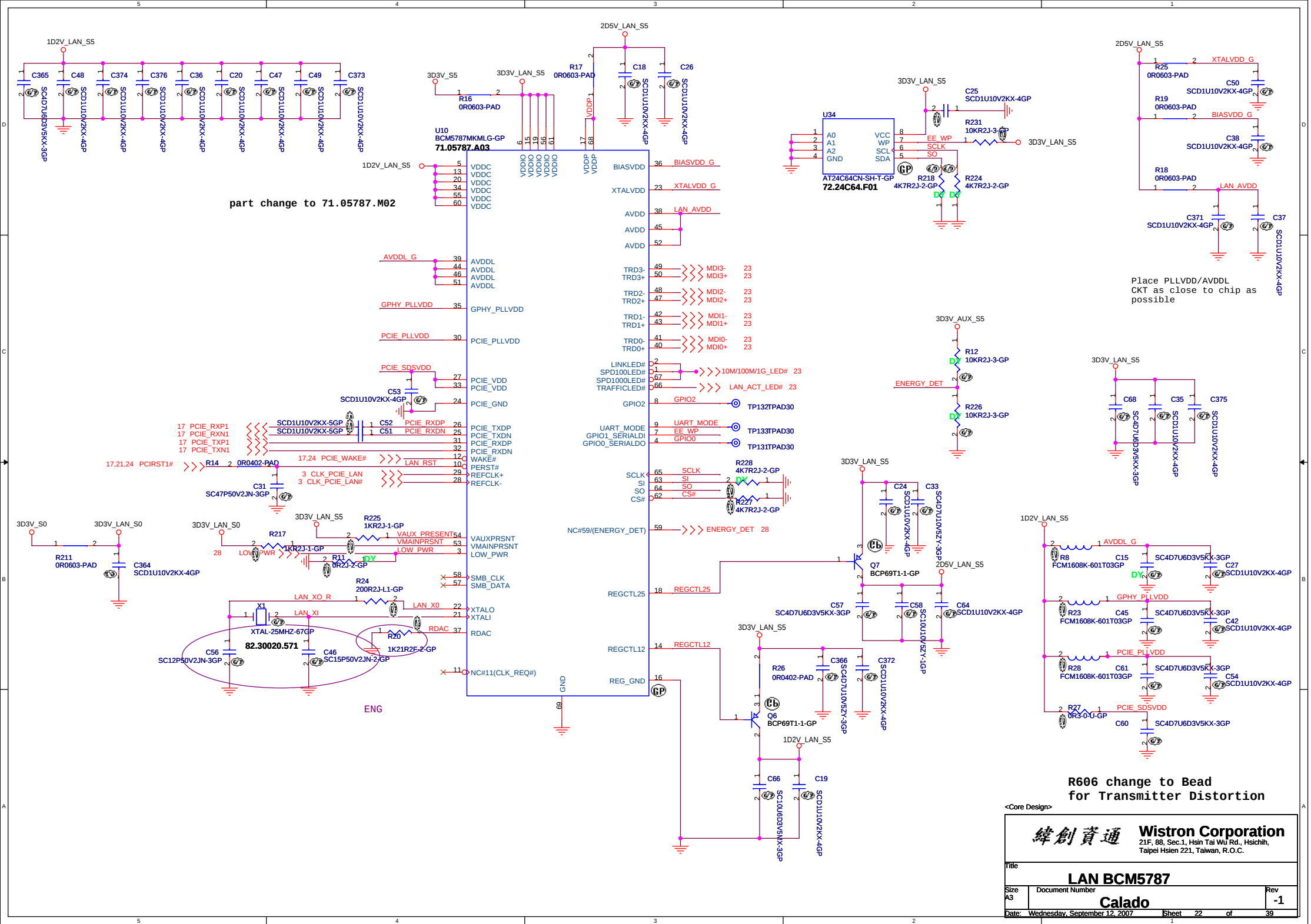


MDC 1.5 CONN



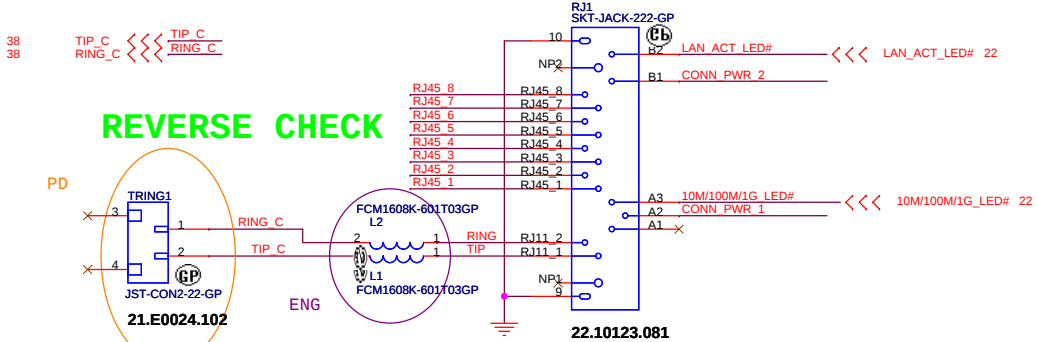
2nd source: 20.F0604.012



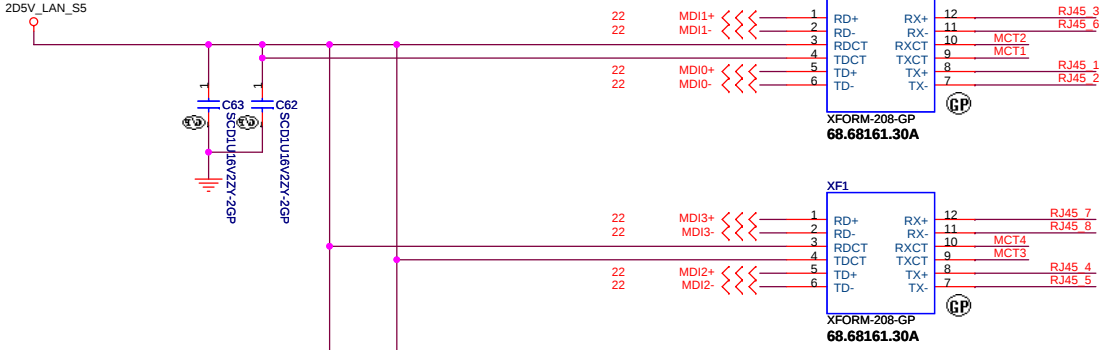


Voltage Rail	4401E	5789	5787
VDDIO_PCI	3D3V_LAN_S5	3D3V_S0	Don't Care
VDDC	1D8V_LAN_S5	1D2V_LAN_S5	
VDDIO	3D3V_LAN_S5	3D3V_LAN_S5	
VESD	3D3V_LAN_S5	3D3V_S0	Don't Care
VDDP	Don't Care	2D5V_S5	
3D3V_2D5V_S5	3D3V_S5	2D5V_S5	
1D8V_1D2V_S5	1D8V_LAN_S5	1D2V_S5	

LAN Connector



GIGA Lan Transformer

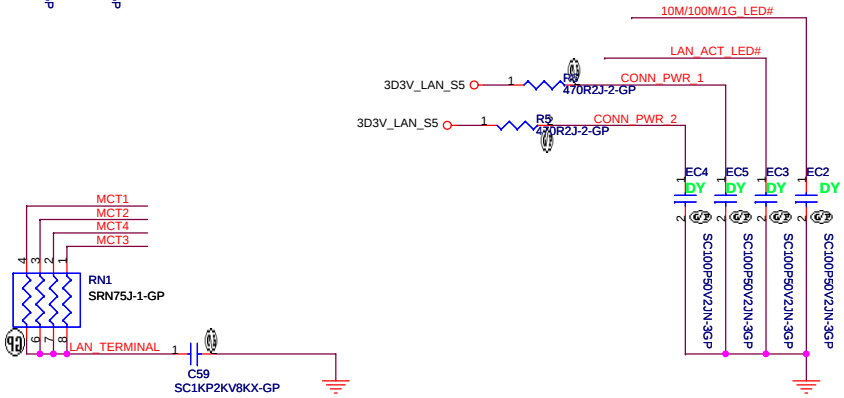


- 1.route on bottom as differential pairs.
- 2.Tx+/Tx- are pairs. Rx+/Rx- are pairs.
- 3.No vias, No 90 degree bends.
- 4.pairs must be equal lengths.
- 5.6mil trace width,12mil separation.
- 6.36mil between pairs and any other trace.
- 7.Must not cross ground moat,except RJ-45 moat.

RJ11 signal must leave the other signal or power plane 100mil.

DOC_TIP,DOC_RING,TIP,RING:
W/S : 10/100 @ Surface layers
10/20 @ Inner layers

10/100 LAN Transformer	RJ45 PIN
TD+ --> TX+	RJ45-1
TD- --> TX-	RJ45-2
RD+ --> RX+	RJ45-3
RD- --> RX-	RJ45-6



A3:Green
B2:YELLOW
LAN Link: Green(A3), behavior is the same for 10/100/1000 bits
LAN Data: Yellow(B2), when LAN is transferring data.

<Core Design>

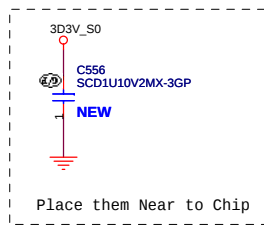
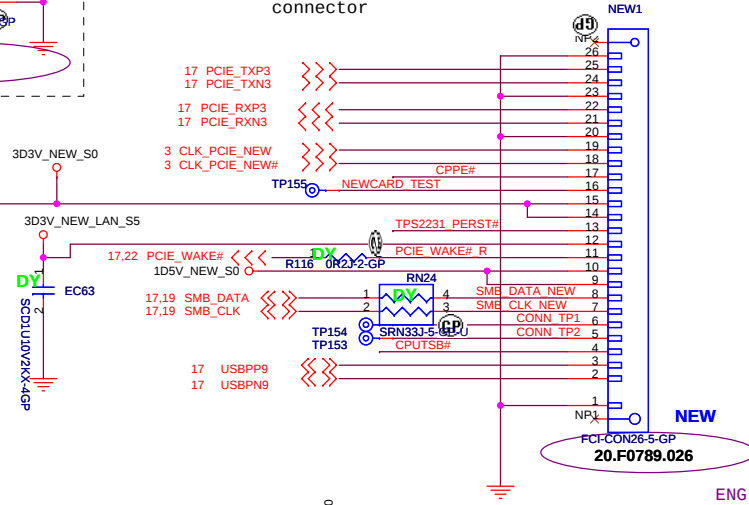
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **LAN Connector**

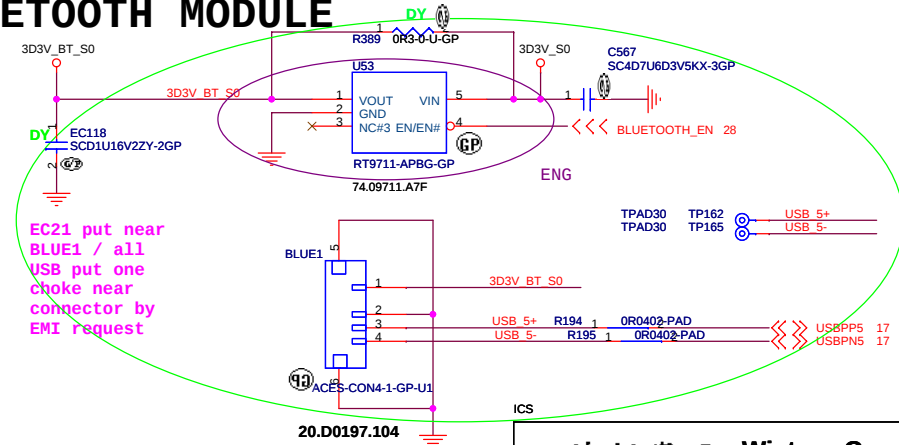
Size A3 Document Number: **Calado** Rev: **-1**

Date: Wednesday, September 12, 2007 Sheet 23 of 39

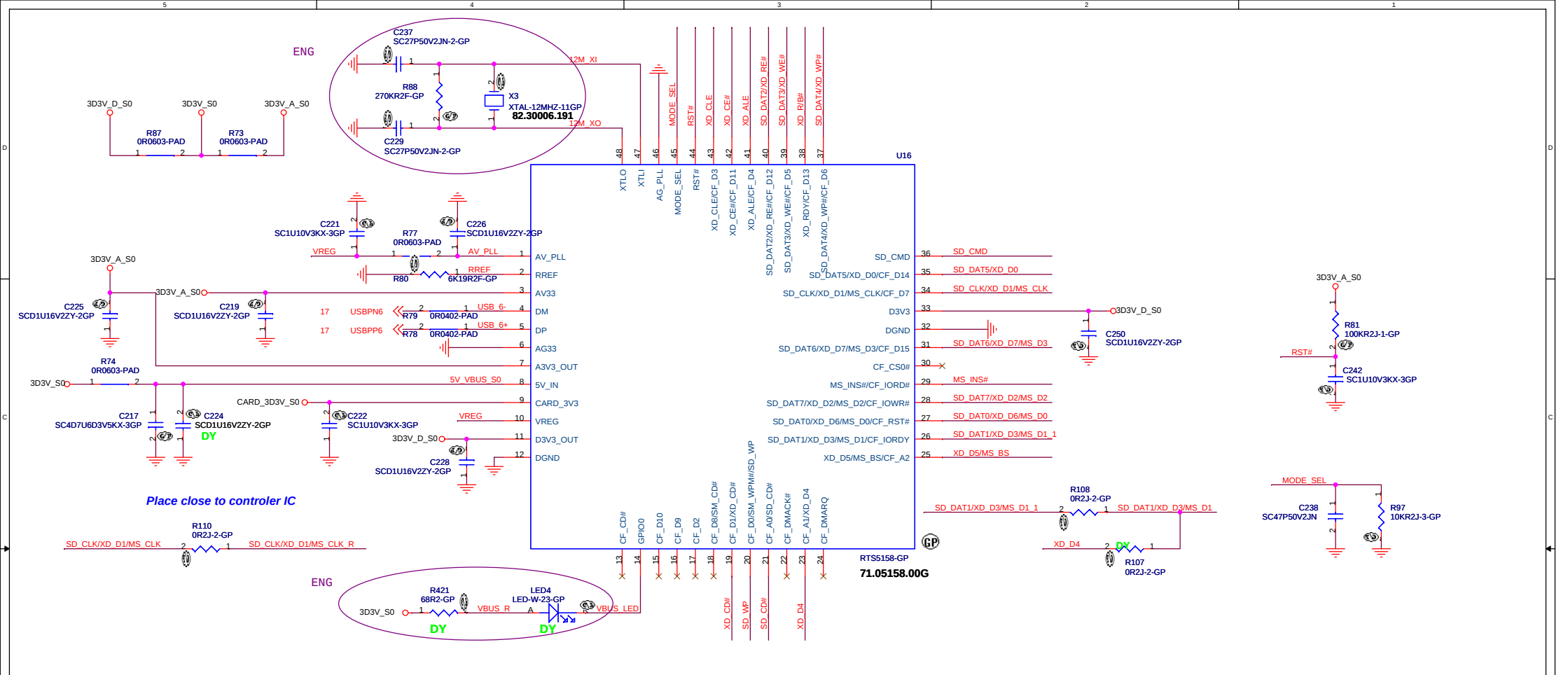
Reserve the symbol
for bottom side
connector



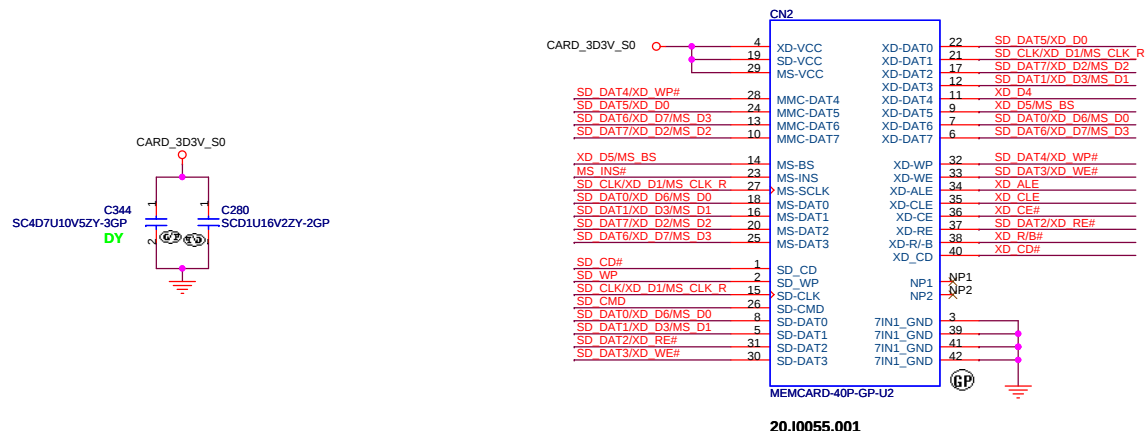
Place them Near to Connector

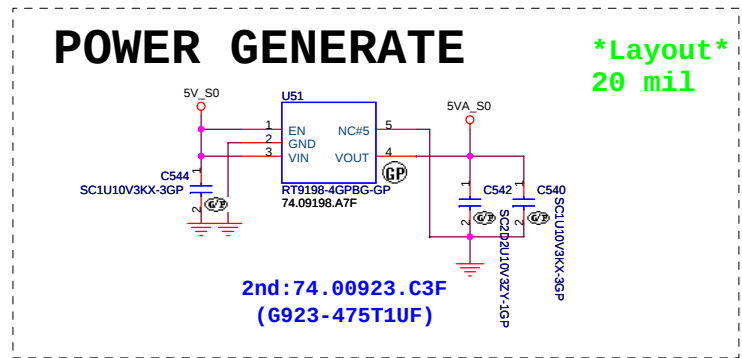
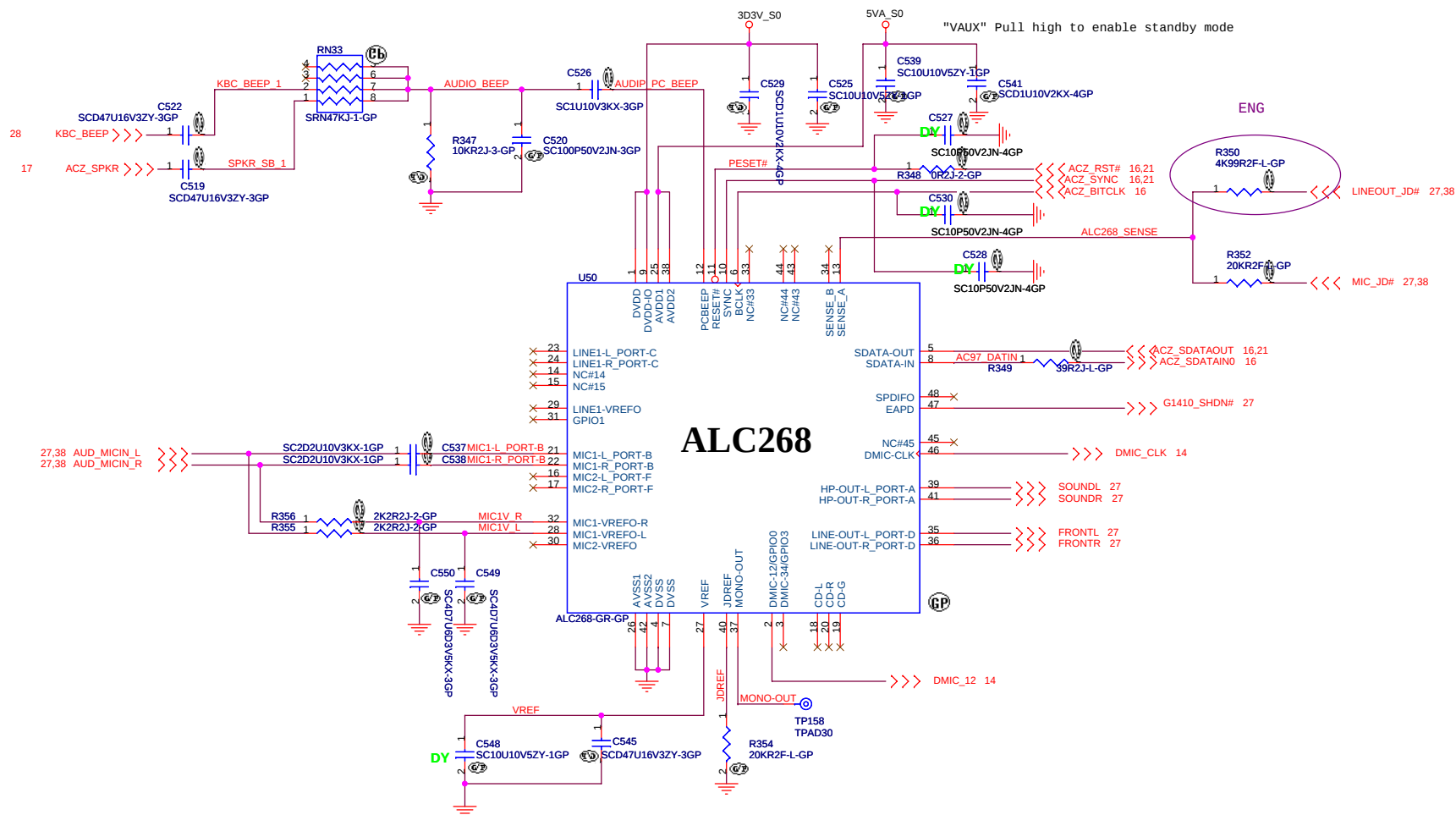


緯創資通 **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

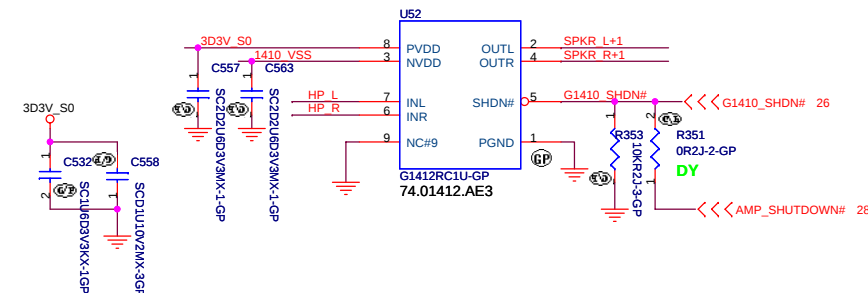
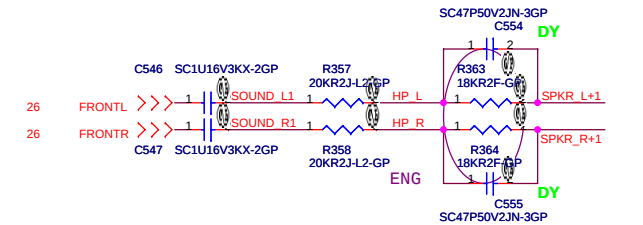
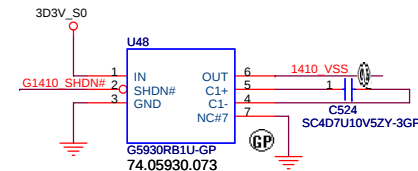
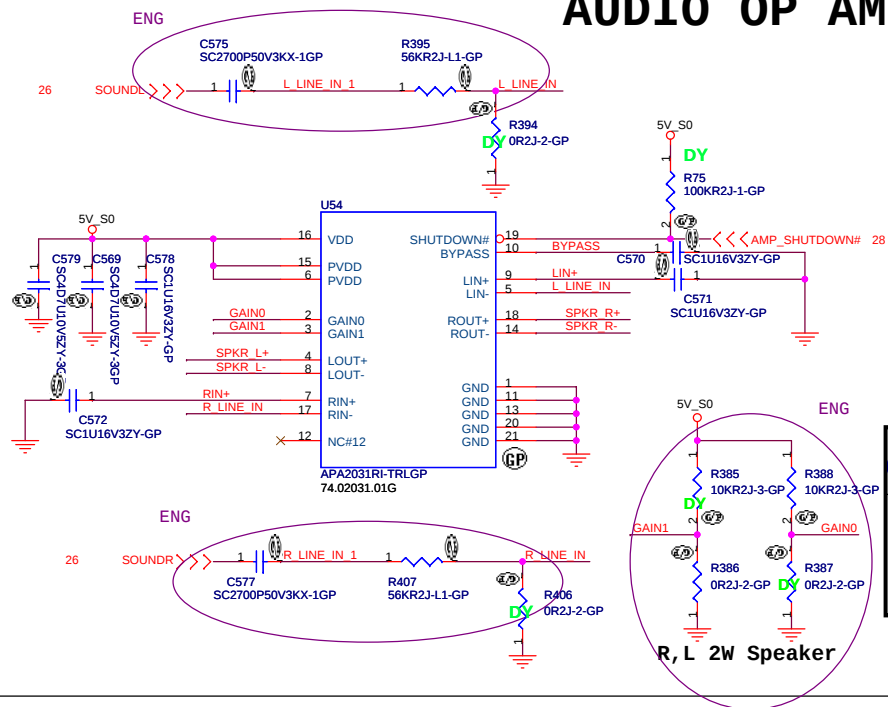


4 IN1 CARD-READER (SD/SD IO/MMC/MMC4.0/MS/MS PRO/XD)

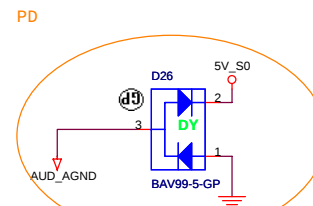
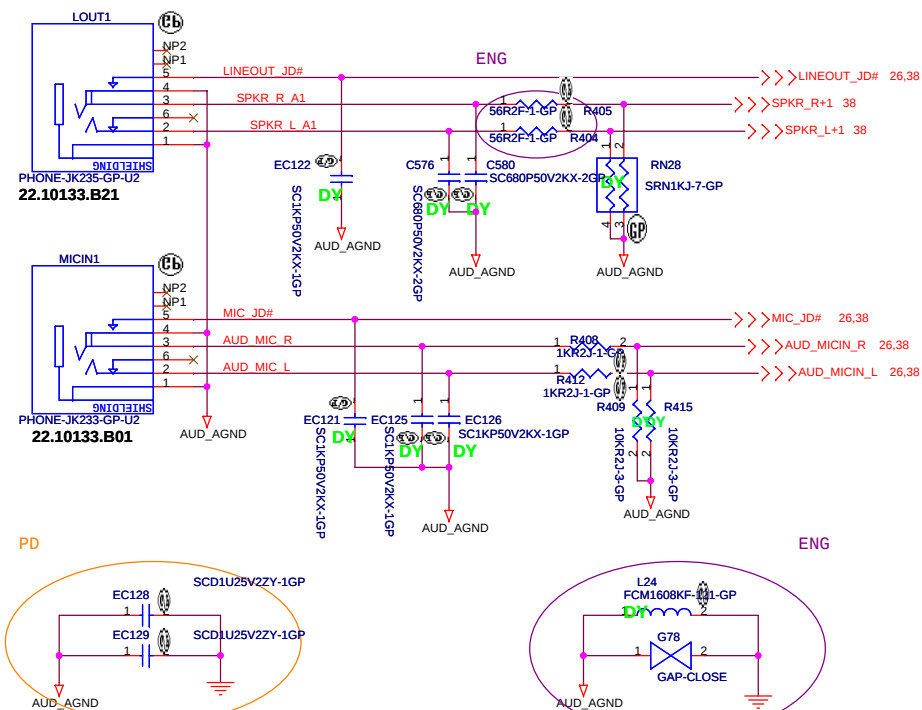




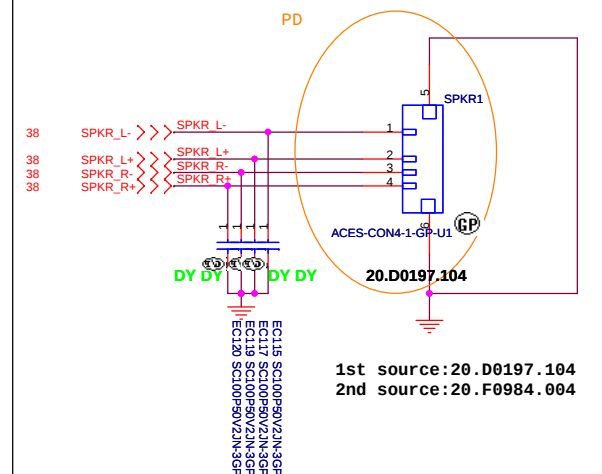
AUDIO OP AMPLIFIER



	GAIN0	GAIN1	Av (dB)
0	0	0	6
0	1	0	10
1	0	1	15.6
1	1	1	21.6

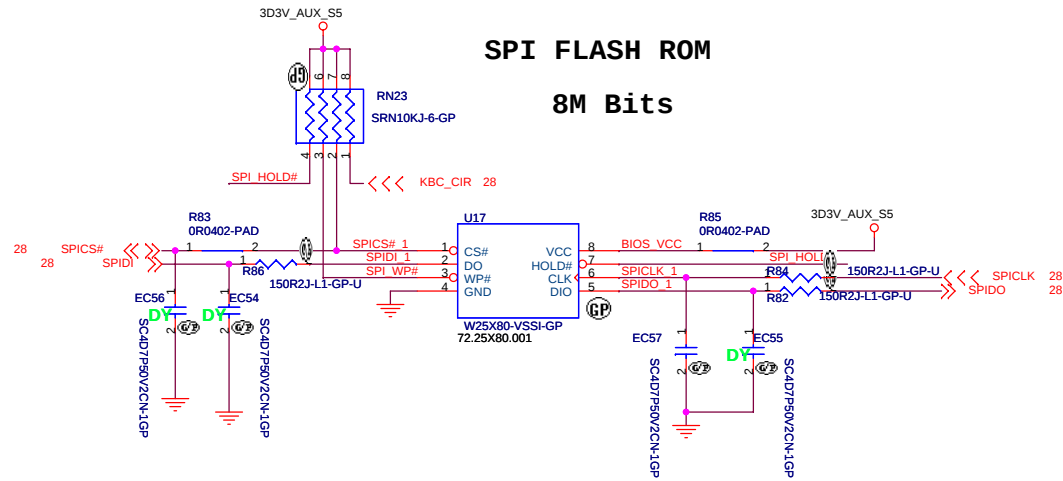


Internal Speaker

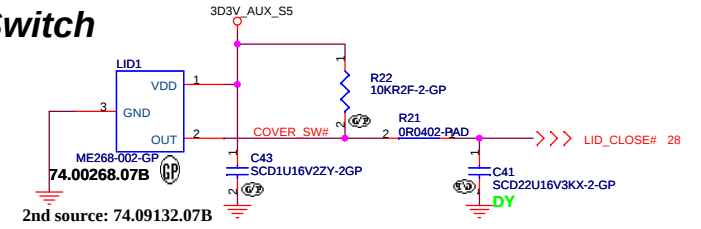




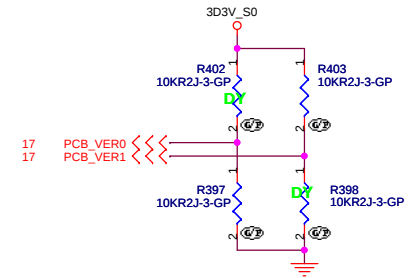
SPI FLASH ROM 8M Bits



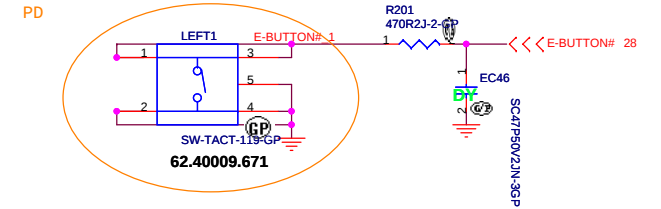
Hall Switch



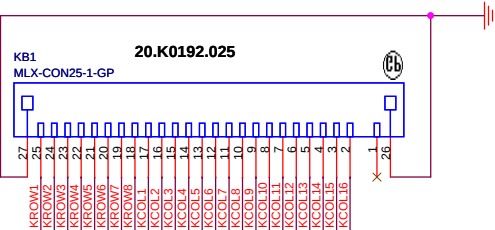
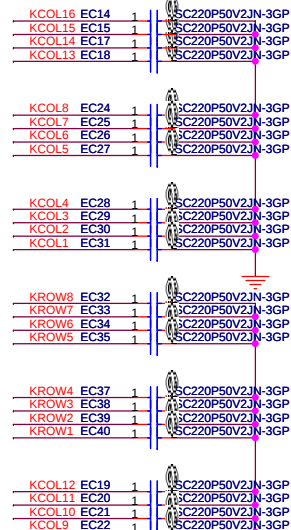
PlanarID
(1,0)
SA: 0,0
SB: 0,1
-1: 1,0
-2: 1,1



E-key



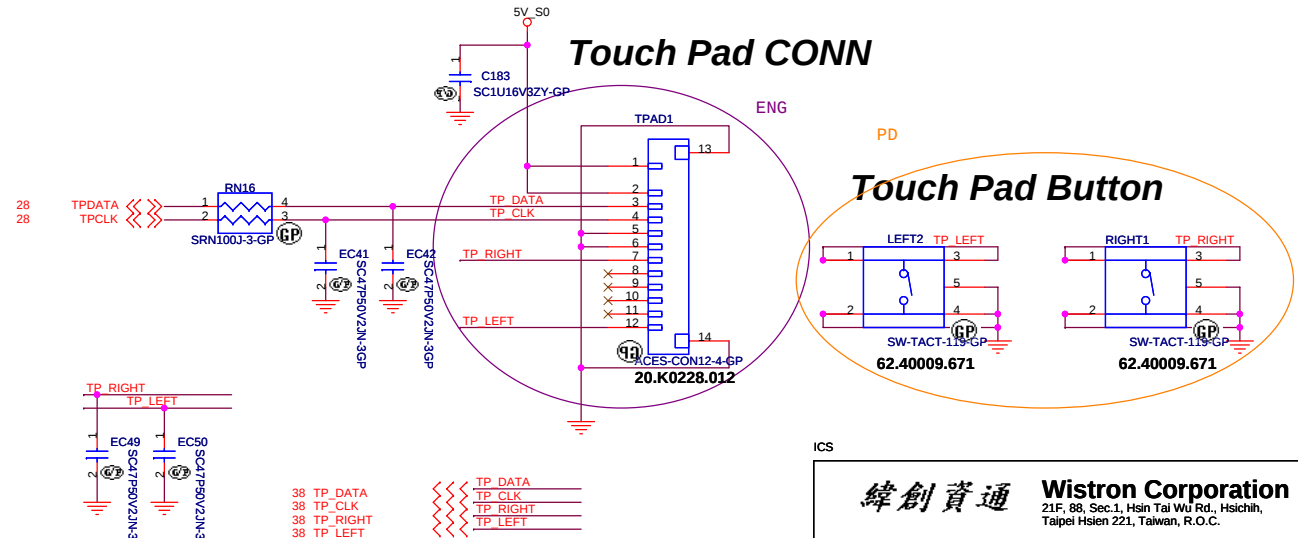
EMI Bypass cap.



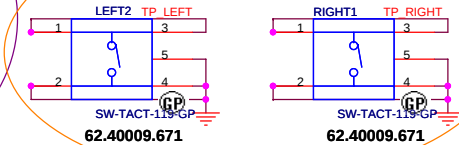
Internal Keyboard CONN



Touch Pad CONN

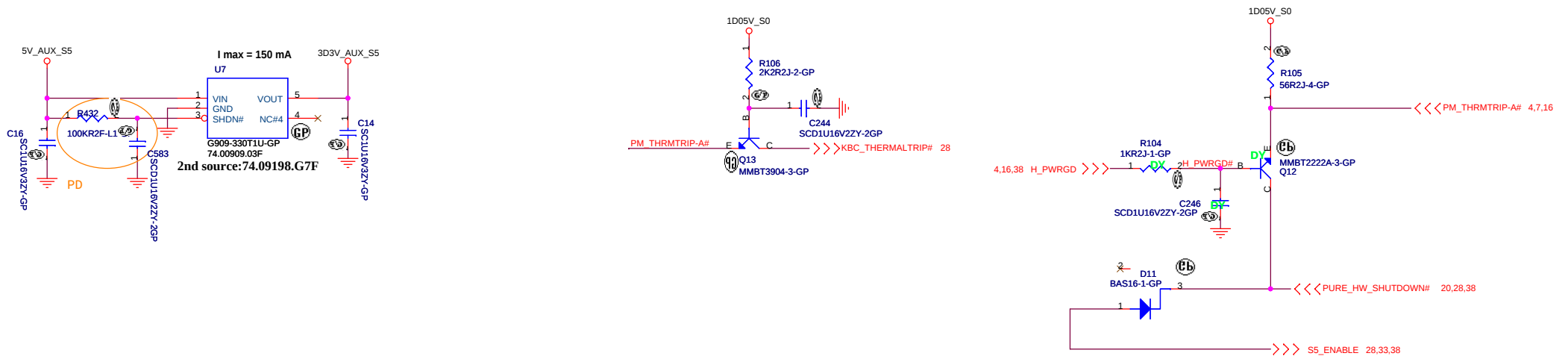


Touch Pad Button

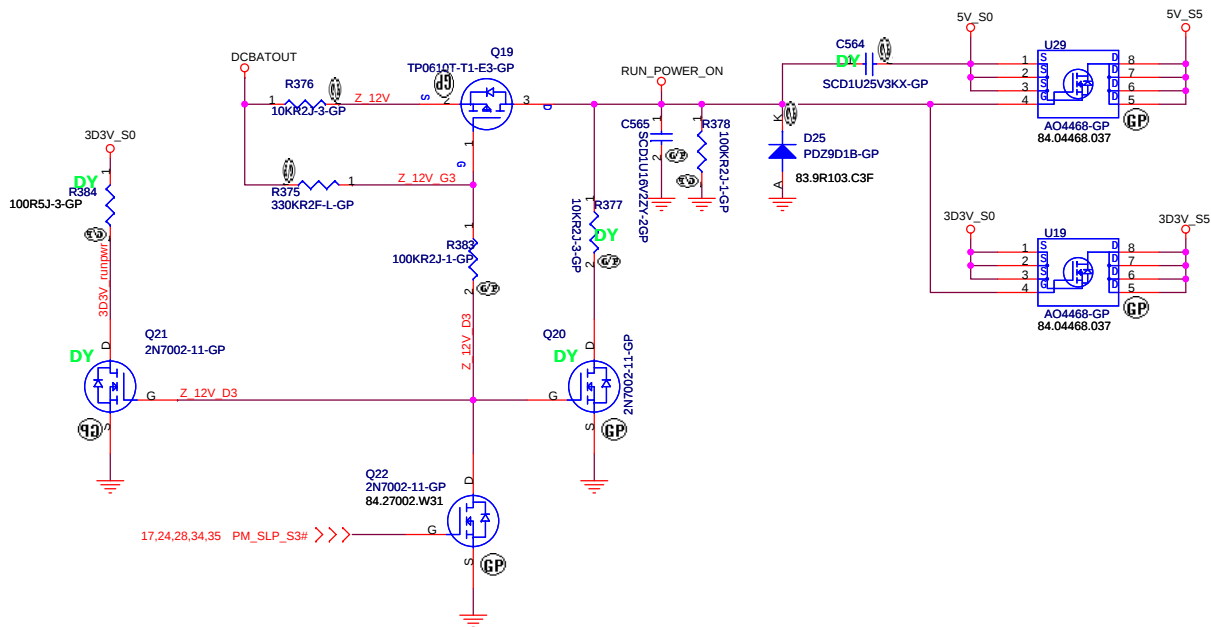


Aux Power

3D3V_AUX_S5



Run Power



ICS

緯創資通

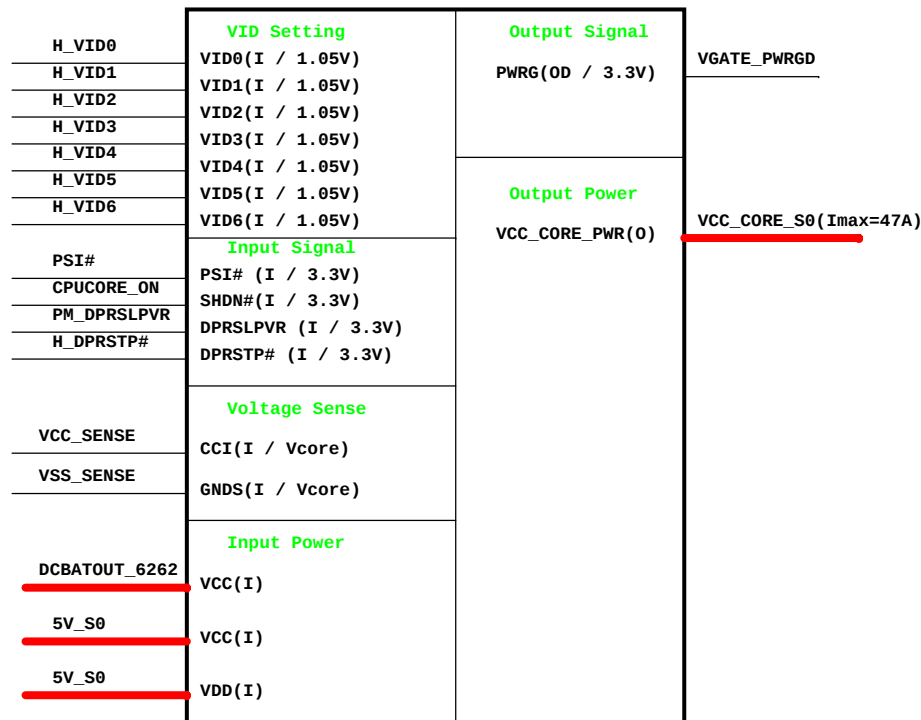
Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title	RUN POWER and 3D3V_AUX_S5
-------	----------------------------------

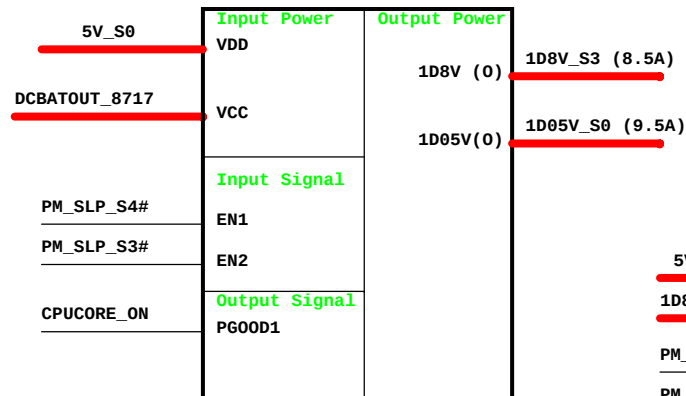
Size	Document Number	Rev
------	-----------------	-----

Date: Wednesday, September 12, 2007 Sheet 30 of 39

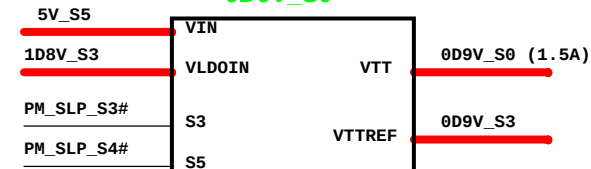
CPU_CORE MAX8770



TPS51124 1D8V/1D05V

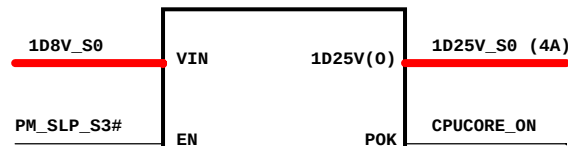


0D9V_S0



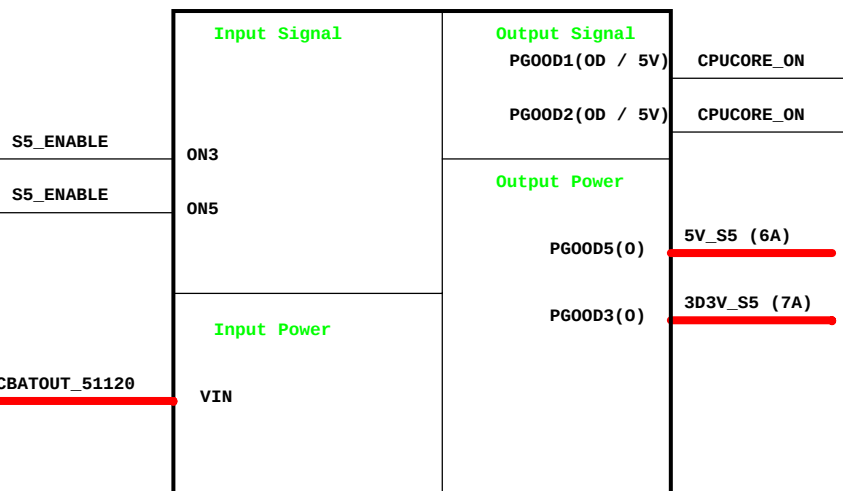
TPS51100

1D25V_S0

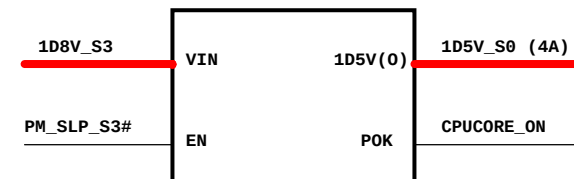


APL5913

TPS51120 5V/3D3V

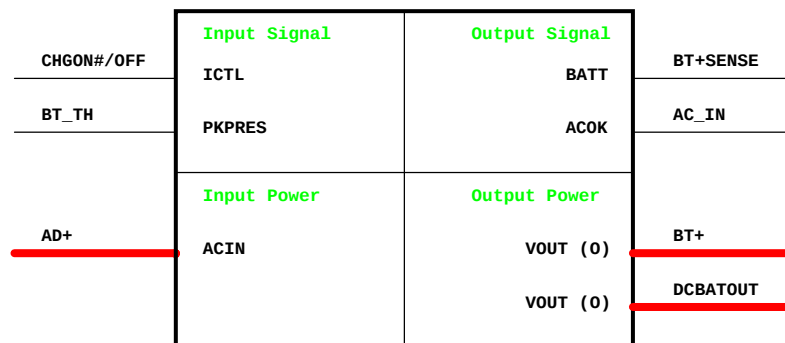


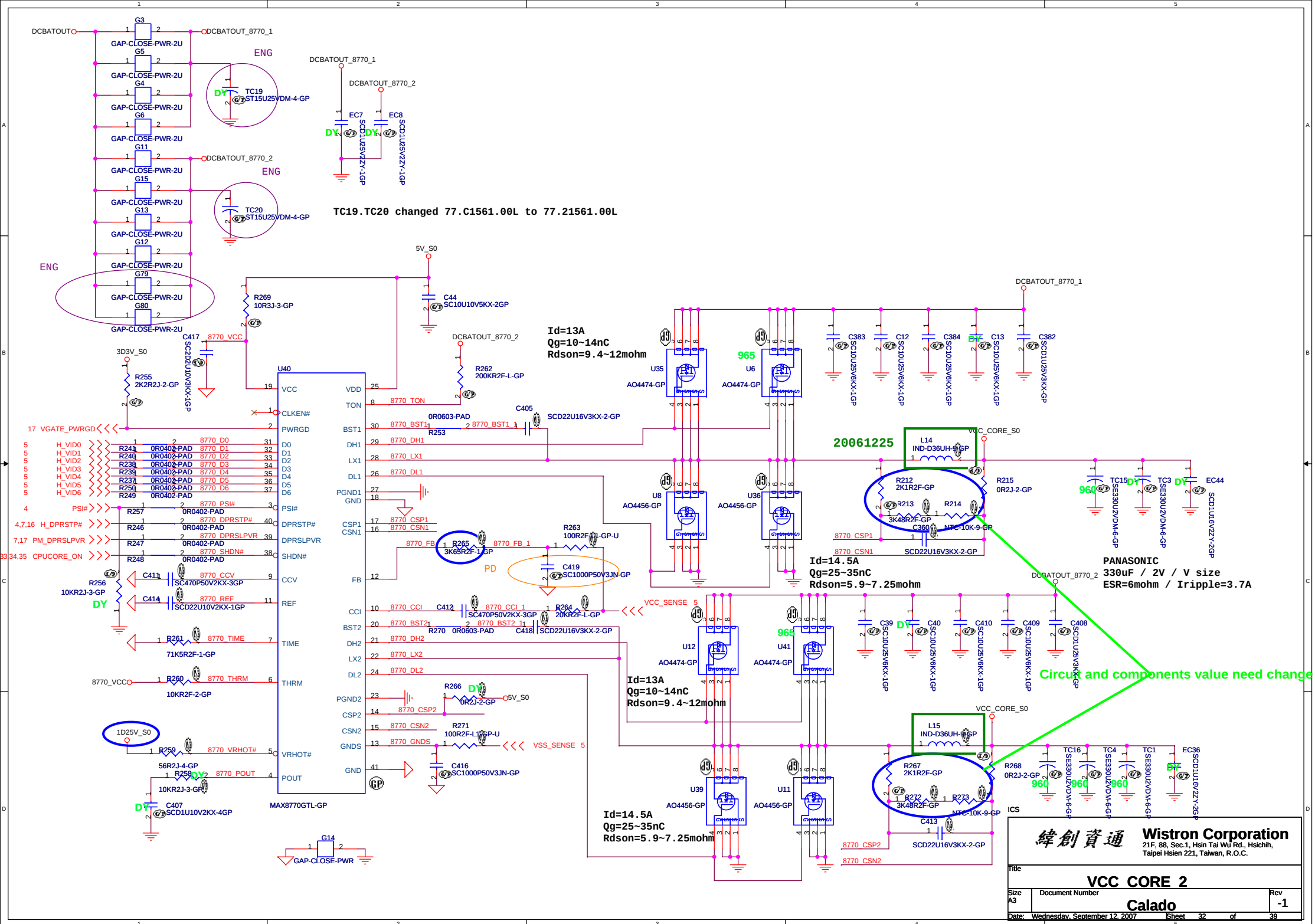
1D5V_S0



APL5915

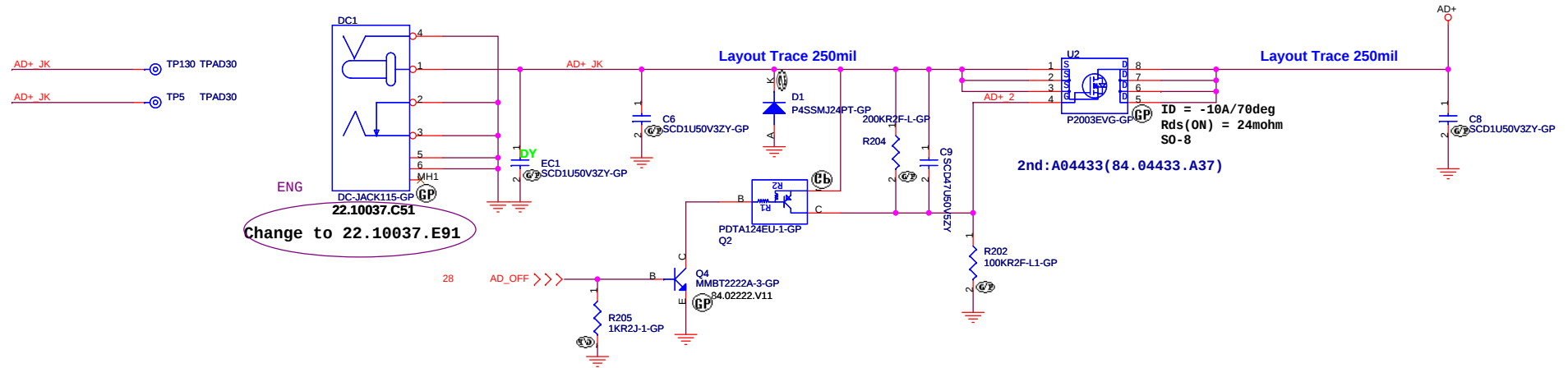
Charger MAX8731



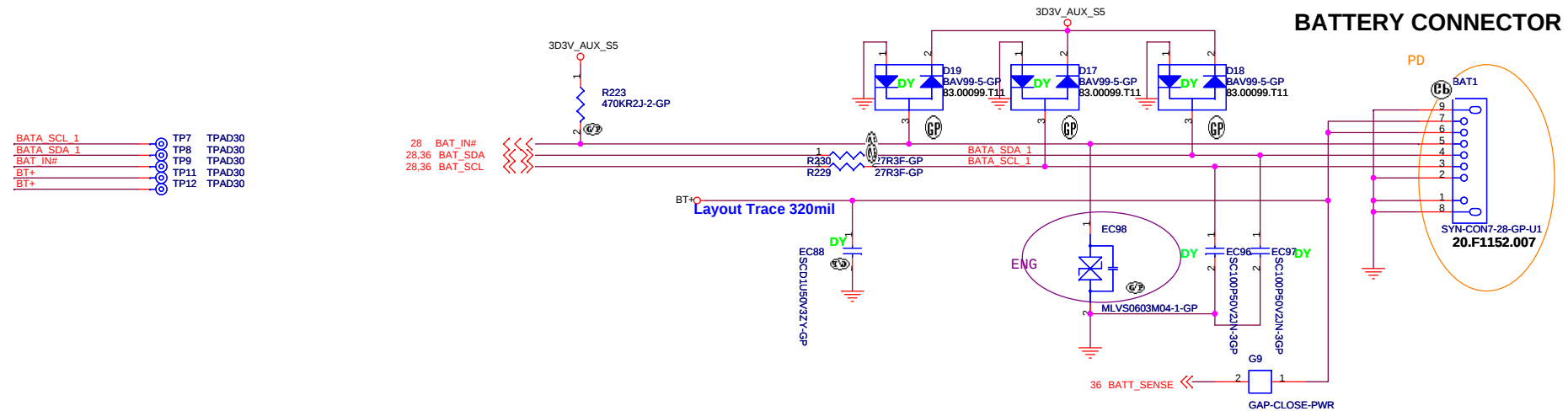




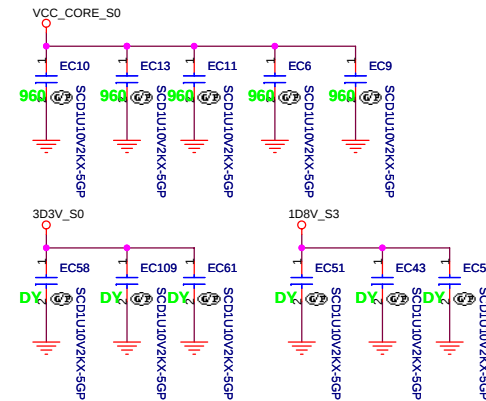
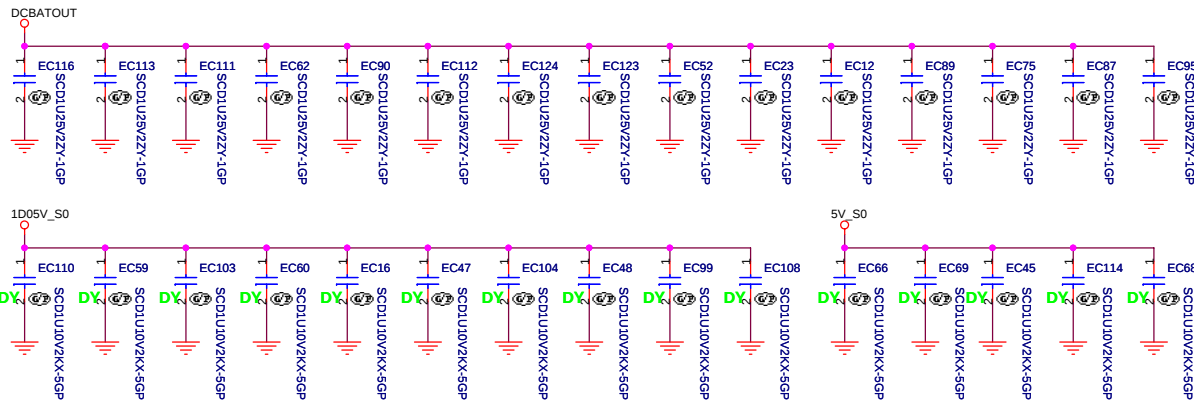
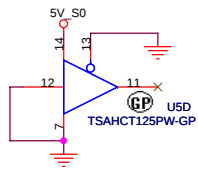
Adaptor in to generate DCBATOUT



BATTERY CONNECTOR



ICS



ENG



PD

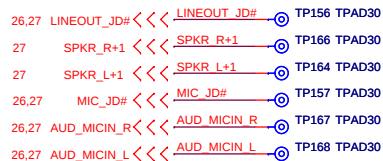


FAN CONN

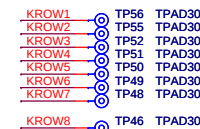
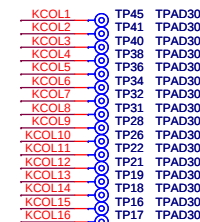


Audio Connector

Internal KeyBoard CONN



Test Point



TRING CONN

Test Point



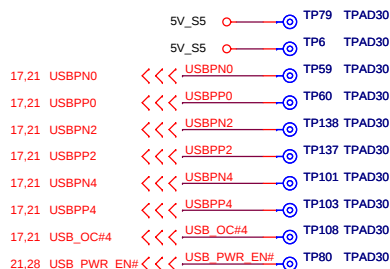
Touch Pad CONN

Test Point near TPAD1

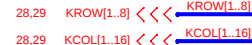


USB ZIF CONN

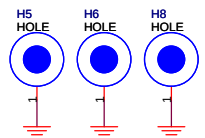
Test Point



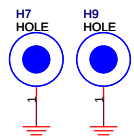
Internal Speaker



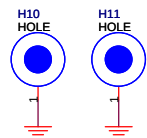
CPU NB MDC MINI CARD



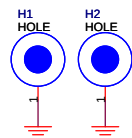
34.42Y01.011



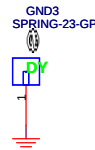
34.42Y01.011



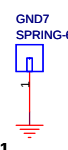
34.42Y01.011



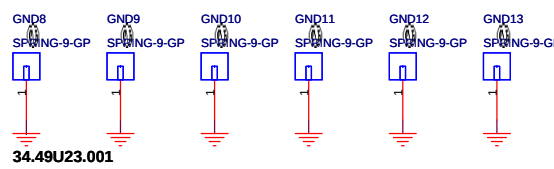
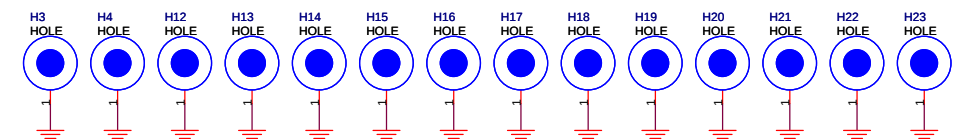
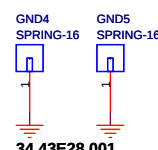
34.46502.001



34.13B01.001



34.43E28.001

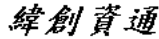


34.49U23.001

Test Point 放在 Dimm Door 打開可量測處

SA to SB
1.TC6 change to 900U
2.modify U42(change to G913 300mA) add R417 for TV CRT ripple.
3.add Q27 for BT LED signal
4.change LED1 to 83.01221.I70(right angle)
5.add U55 BLON_5V for LED panel
6.change U1 to 74.04280.C9P for source request
7.add polyswitch F3 for safety.
8.C338 C339 C341 C340 change to 0402 size for SATA signal.
9.FAN1 change to 20.F1000.003 for ME.
10.USB1 swap pin3 pin4 signal.
11.USB2 USB3 change to 22.10218.R31 for ME.
12.add polyswitch F4 F5 for safety.
13.change U4 U45 to 74.09711.B7F ,U56 U57 74.05250.C7F for source request.
14.R20 change to 1.21K for IEEE.
15.C56 change to 12P for Oscillation report.
16.U53 change to 74.09711.A7F for source request.
17.NEW1 change to 20.F07890.026.SK1 change to 21.H0153.001 for ME
18.add R421 LED4 for CardReader test.
19.C237 C229 change to 27P for Oscillation report.
20.R350 change to 4.99K for jack detection.
21.R363 R364 change to 18K.R404 R405 change to 56 ohm for audio report.
22.add AUD_AGND.L24 for audio niose.
23.C575 C577 change to 2700p Cut frequency at 500HZ
24.add BT_LED to KBC GPIO50.
25.add TC19 TC20 TC21 TC22 TC23 TC24 for acoustic noise.
26.C419 change to 1000p for power team.
27.U21 change to 84.04712.037.L9 change to 68.3R310.20A for power team.
28.R151 change to 16.5K.R124 change to 13K for OCP.
29.L7 change to 68.1R510.10J for power team.
30.R379 change to 10K.R381 change to 7.5K for OCP.
31,BAT1 change to 20.80977.007 for ME.
32.EC98 add 69.80007.031 for EC damaged.
33.R402 change to 10K.R397 DY for planar ID.
34.ODD1 change to 20.80967.050 for ME.
35.add G79.G80 for power.
36.R385.R386.R388.R387 change for Gain.R395.R407 change to 56K.
37.add EC6.EC9.EC10.EC11.EC13 to 960 for EMI.
38.add EC41.EC42.EC49.EC50.EC127 for EMI.
39.add R423.R422 for EMI.
40.add RN34.RN35.RN36 for EMI.
41.remove Golden finger
42.swap Touchpad pin define.
43.change L1 L2 to 68.00084.371.
44.change DC1 to 22.10037.E91 for ME.
45.change TVOUT1 to 22.10021.F41 for ME.
SB to -1
1.add AFTE test point for power board Conn.
2.add R432.C583 change G47 to R433 for 3D3V_AUX_S5 power option
3.change to 0 ohm pad for R45.R41.R216.R391.R183.R184.R14.R162.
R78.R79.R74.R87.R73.R77.R390.R21.R194.R187
4.change SPKR1 to 20.D0197.104 for ME.
5.change TRING1 to 21.E0024.102 for ME.
6.remove D7.D8.D9 for EMI.
7.add EC116.EC113.EC111.EC62.EC90.EC112.EC124.EC123.EC52.EC23.EC12.EC89.EC75.EC87.EC95.
8.change R422.R423 to 33 ohm.add EC71.EC72 to 33P for EMI.
9.add EC128.EC129 for EMI.
10.change c419 to 78.10234.1BL for source OBSOLETED.
11.change LEFT1.LEFT2.RIGHT1 to 62.40009.671 for ME.
12.change TVOUT1 to 22.10021.H61 for ME.
13.change BAT1 to 20.F1152.007 for ME.
14.add D26 for EMI.
15.change TC17 to 79.22710.3AL for USB droop test fial.
16.change TC2.EC84 to 5V_USB3_S0_1,change TC17.EC101 to5V_USB2_S0_1 for UPT2 fail.
17.add GND6.GND7.GND8.GND9.GND10.GND11.GND12.GND13 fot EMI.
18.change CRT1 to 20.20378.015 for ME.
19.del GND1.GND2.

ICS

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
Change List			
Size	Document Number		Rev
Calado		-1	
Date: Thursday, September 13, 2007			
Sheet	39	of	39